

J7VCL SOM - TPS65941x + LP8764x PMICs

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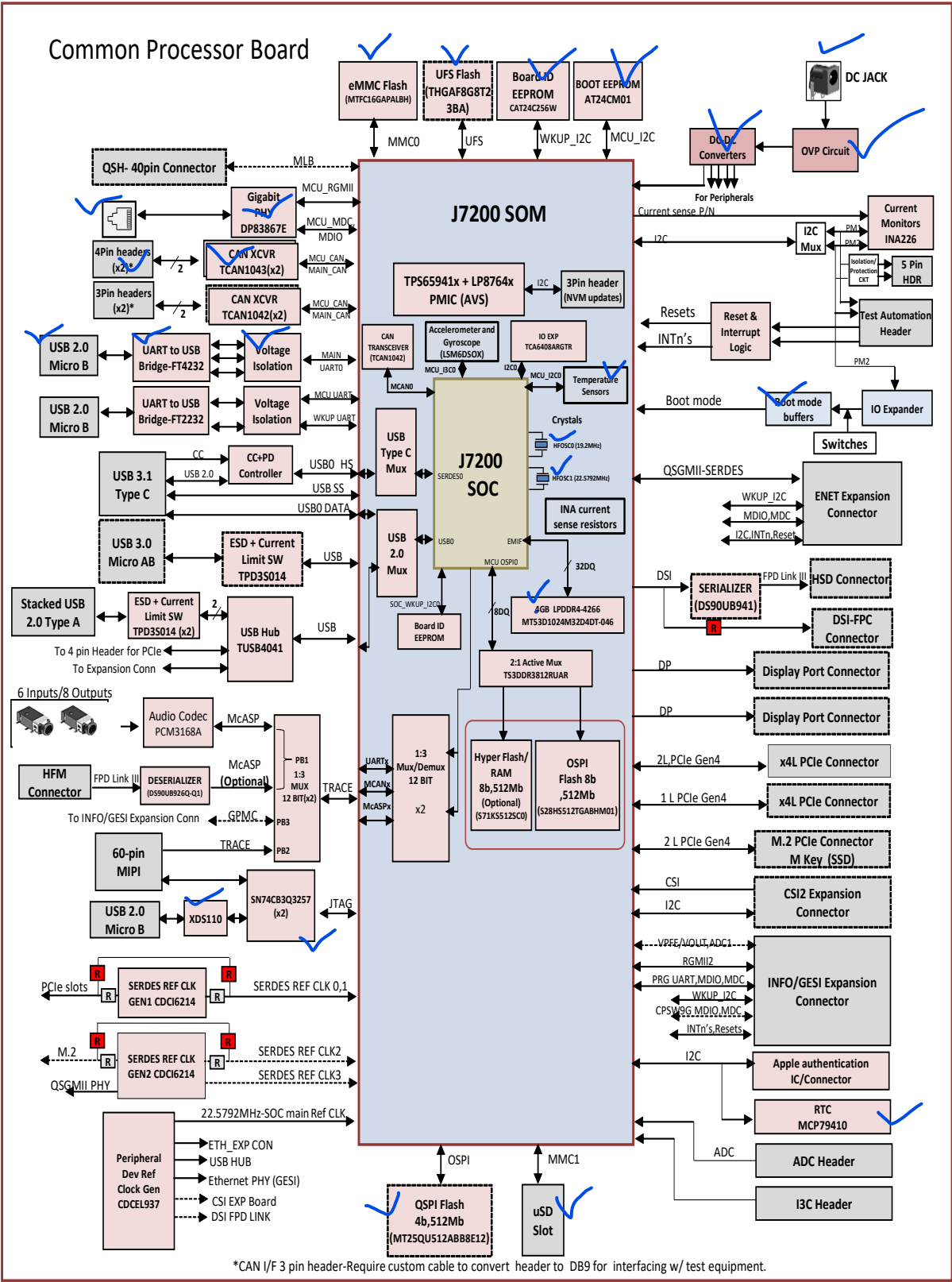
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REVISION HISTORY

REV #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
E6	20 AUG 2020	Drafted from PROC105E5 Added PU resistor 10K on FET Q1 Pin 1 (PU to VCCA_3V3) Disconnected the Gyro Interrupt function on Bootmode6 (DNI'd the resistors R150 & R154) Added 0.47uF, 0402 (PN: GCM155C71A474KE36D) to VDDR_IO_DV power rail Added GND Test points for major supplies and signals	Mistral Design Team		
	24 AUG 2020	Added AND Gate U129 for SOC_PORz_OUT logic Updated System Block diagram	Mistral Design Team	TI	
	25 AUG 2020	Removed the additional circuitry added for Interposer (TP39,TP58,TP66,R253,C199,C198,C371 & C372) Removed the ACC3 (Heat sink)	Mistral Design Team		
	26 AUG 2020	Removed the SMD Test points TP226, TP214, TP230 & TP218	Mistral Design Team		
	27 AUG 2020	Removed the DDR SI coupon replica traces D22 and CA5	Mistral Design Team		
	23 SEP 2020	Updated the Murata parts with received samples	Mistral Design Team		
	28 SEP 2020	Added alternate P/N for I3C sensor MOD1 and text clean up done	Mistral Design Team		

SYSTEM BLOCK DIAGRAM



TPS65941x-Q1 + LP8764x-Q1 PMICs POWER FLOW DIAGRAM

Recommended for Superset Use Case max power

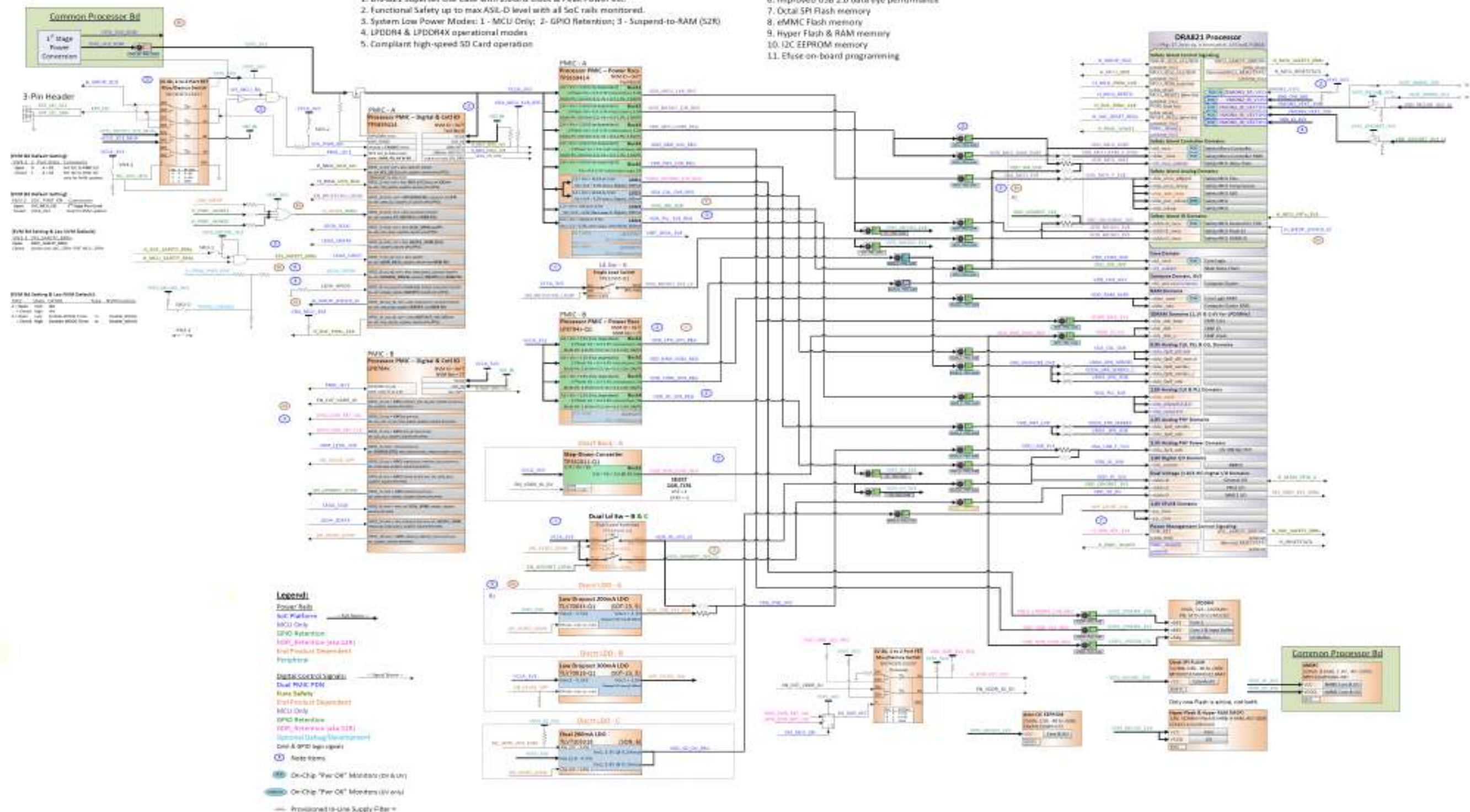
DRA821 EVM Leo+Hera SoC PDN-0A Details

0.01 05/06/2020 Initial PDN

(Power Rail & GPIO Mapping Overview)

Features Supported:

1. DRA821 Superset Use Case with 2.0GHz clock & Peak Power out.
2. Functional Safety up to max ASIL-D level with all SoC rails monitored.
3. System Low Power Modes: 1 - MCU Only; 2 - GPIO Retention; 3 - Suspend-to-RAM (S2R).
4. LPDDR4 & LPDDR4X operational modes
5. Compliant high-speed SD Card operation
6. Improved USB 2.0 data eye performance
7. Octal SPI Flash memory
8. eMMC Flash memory
9. Hyper Flash & RAM memory
10. I2C EEPROM memory
11. Fuse-on-board programming



Project :
J7 EVM



Title
TPS65941+ LP8764x-Q1 POWER FLOW DIAGRAM

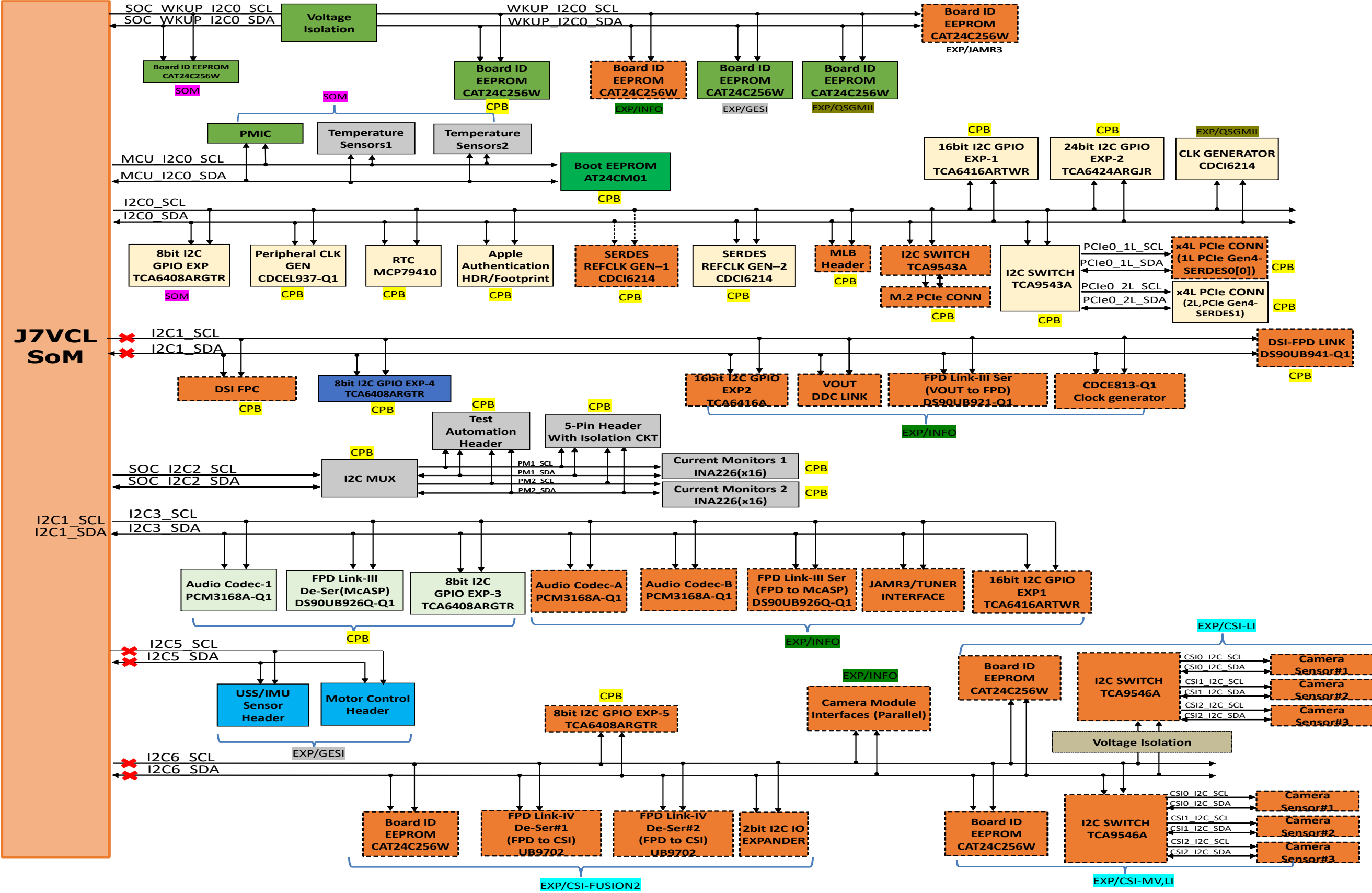
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C PROC105 001 J7200XSOMG01EVM

Date: Friday, August 21, 2020

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SoM I2C TREE DIAGRAM



SoM I2C ADDRESS TABLE

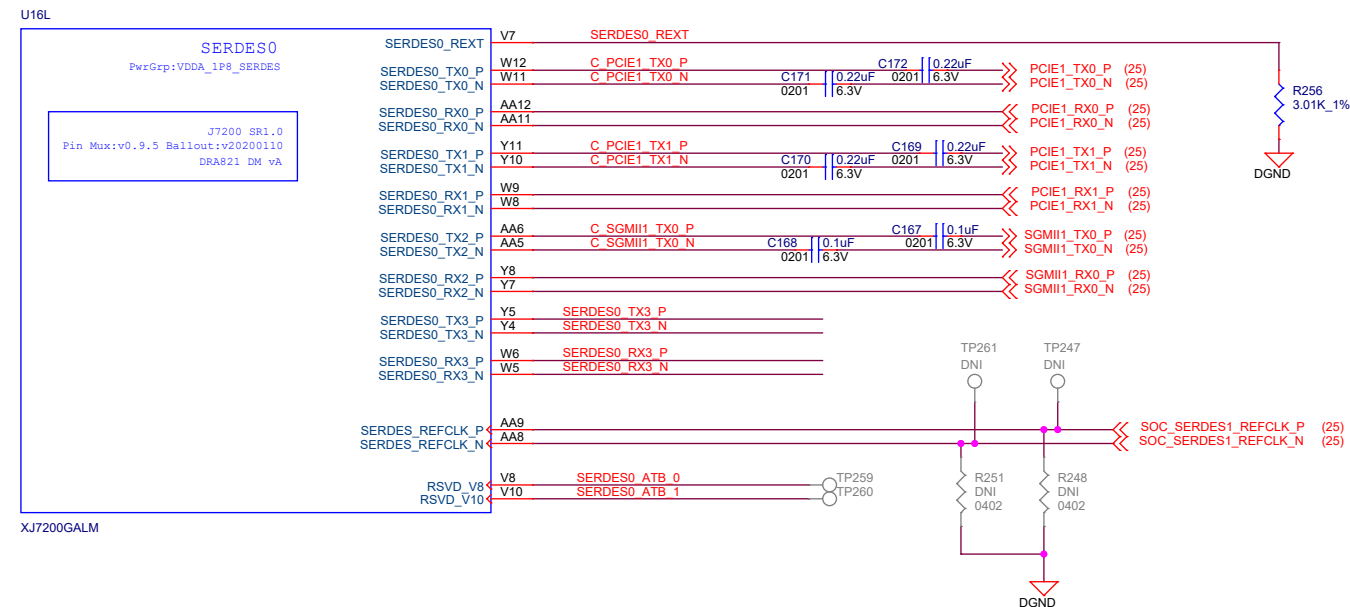
J7200 SoM I2C mapping						
SL NO.	Board	Interface name	Part#	Address	J721E/CPB Port mapping	J7200 Port mapping
1	EVM/SoM	Board ID EEPROM	CAV24C256WE-GT3	0x50	WKUP_I2C0	WKUP_I2C0
2	EVM/CPB	Board ID EEPROM	CAT24C256W	0x51		
3	EXP/GESI	Board ID EEPROM	CAT24C256W	0x52		
4	EXP/QSGMII	Board ID EEPROM	CAT24C256W	0x54		
5	EVM/SoM	PMICs	PMIC A: TPS659414F3 PMIC B: LP8764-Q1	PMIC A: 0x48 to 4B PMIC B: 0x4C to 4F	MCU_I2C0	MCU_I2C0
6	EVM/SoM	Temperature Sensors	TMP100NA/3K	0x48, 0x49		
7	EVM/CPB	Boot EEPROM	AT24CM01	0x50, 0x51	Main I2C0	Main I2C0
8	EVM/SoM	8-bit I2C GPIO Expander	TCA6408ARGTR	0x21		
9	EVM/CPB	SerDes Clock gen #2	CDCI6214	0x77,0x76		
10	EVM/CPB	Peripheral Clock Gen	CDCEL937-Q1	0x6D		
11	EVM/CPB	16bit I2C GPIO EXPANDER1	TCA6416ARTWR	0x20		
12	EVM/CPB	24bit I2C GPIO EXPANDER2	TCA6424ARGJR	0x22		
13	EVM/CPB	Apple Authentication Header	2214BR-10G	0x10, 0x11		
14	EVM/CPB	RTC 7'b	MCP79410	0x57, 0x6F		
15	EVM/CPB	I2C MUX for both x2LANE and x1LANE PCIe Interface	TCA9543APWR	0x70		
16	EXP/QSGMII	QSGMII PHY Ref Clock Generator (QPENET Board)	CDCI6214	0x77		
17	EVM/CPB	I2C Switch for Automation header	NA	0x22	Main I2C2	Main I2C2
18	EVM/CPB	Current Monitors and Header	NA	0x40 to 0x4F (PM1 and PM2 via I2C Switch)		
19	EVM/CPB	8bit GPIO Expander3	TCA6408ARGTR	0x20	Main I2C3	Main I2C1
20	EVM/CPB	FPD Link iii Deserializer	DS90UB926Q-Q1	0x2C		
21	EVM/CPB	AUDIO IF Codec	PCM3168A-Q1	0x44		

GPIO MAPPING TABLE

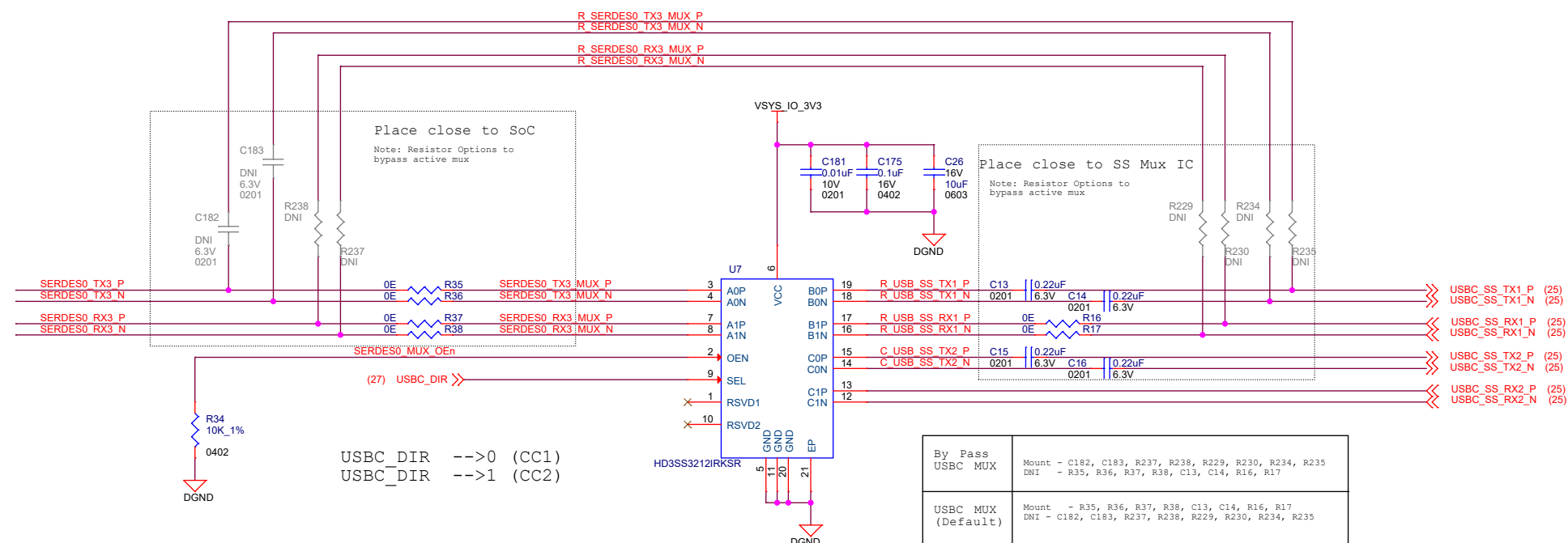
WKUP Domain						
Package Signal Name	GPIO Number	Net name	Input/Output	Default	State	Remarks
WKUP_GPIO0_0	WKUP_GPIO0_0	MCU_MCAN0_EN	Output	BOOTMODE	Active High	MCU CAN0 Enable
WKUP_GPIO0_1	WKUP_GPIO0_1	BOOT_EEPROM_WP	Output	BOOTMODE	Active High	Boot EEPROM Write protect
WKUP_GPIO0_2	WKUP_GPIO0_2	MCU_CAN1_STB	Output	BOOTMODE	Active High	MCU CAN1 Standby
WKUP_GPIO0_3	WKUP_GPIO0_3	GPIO_MCU_RGMII1_RST#	Output	PU	Active low	MCU_RGMII1_Reset
WKUP_GPIO0_6	WKUP_GPIO0_6	OSPI/HYPER_MUX_SEL	Output	DIP_SEL	NA	Flash Memory Selection ('0' - OSPI0, '1' - Hyperflash + HyperRam)
WKUP_GPIO0_7	WKUP_GPIO0_7	SYS_IRQz	Input	PU	Active low	Push-button Interrupt, User Defined/Wake S2R ('0>1' - interrupt pending, '1' - normal operation)
MCU_OSPI0_LBCLKO	WKUP_GPIO0_17	MCU_OSPI0_ECC_FAIL	Output	NA	Active High	OSPI_ECC_FAIL (Mux option w/ HYPERBUS_CKn), MCU_OSPI0_ECC_FAIL is DNI resistor option.
MCU_SPI0_CLK	WKUP_GPIO0_56	PROFI_UART_SEL	Output	BOOTMODE	Active High	Signal Mux Control ('0' - Profibus, '1' - BP/MC UART)
MCU_SPI0_D0	WKUP_GPIO0_57	SYS_MCU_PWRDN	Output	BOOTMODE	Active low	System Power Down ('0' - normal operation, '1' - system power down)
MCU_SPI0_D1	WKUP_GPIO0_58	MCU_CAN0_STBz	Output	BOOTMODE	Active low	MCU CAN0 Standby
MCU_SPI0_CS0	WKUP_GPIO0_59	MCU_RGMII1_INT#	Input	PU	Active Low	MCU Ethernet Interrupt ('0' - interrupt pending, '1' - no interrupt)
WKUP_GPIO0_77	WKUP_GPIO0_77	LEOB_GPIO7	Output	BOOTMODE	NA	Spare GPIO of PMIC. Function TBD
WKUP_GPIO0_78	WKUP_GPIO0_78	H_MAIN_GPIO_A	Output	BOOTMODE	NA	GPIO10 of PMIC B. Function TBD
WKUP_GPIO0_80	WKUP_GPIO0_80	LSM6DSOX_INT	Output	BOOTMODE	NA	Interrupt from I3C Gyroscope sensor
WKUP_GPIO0_84	WKUP_GPIO0_84	H_MCU_INT#	Input	PU	Active low	Interrupt from PMIC
Main Domain						
EXTINTn	GPIO0_0	SOC_EXTINTN	Input	PU	Active low	Push-button Interrupt, User Defined
MCAN1_RX	GPIO0_12	CANIO_RET_WAKE	Input	PU	NA	Push-button wake signal,
MCAN9_RX	GPIO0_28	GPIO_RGMII2_RST	I/O	NA	NA	Routed to INFO/GESI expansion connector. GESI - Used for GPIO_PRG0_RGMII_RST; INFO - Not used
MCAN7_RX	GPIO0_24	C_MCASPO_AFSR	NA	PU	Active low	I2C0 IO expander interrupt. ('0' - interrupt pending, '1' - no interrupt) (I2C0_IOEXP_INT#) Note: GPIO only available from Trace/GPMC Mux
SPI0_D1	GPIO0_55	SEL_SDIO_3V3_1V8n	Output	NA	Active low	SW controls & transition SD card to high speed 1.8V signalling if card type supports
GPMC0_CLK	GPIO0_44	PM_I2C_SEL	Output	PD	NA	CP Board - PM I2C Mux selection. ('0' - SOC_I2C2_SCL/SDA -> PM1_SCL/SDA, '1' - SOC_I2C2_SCL/SDA -> PM2_SCL/SDA) GESI - Boosterpack_GPIO1
RMII1_CRS_DV	GPIO0_4	ENET_EXP_INTB	Input	PU	Active low	Ethernet Expansion Interrupt. ('0' - interrupt pending, '1' - no interrupt)
MCAN9_TX	GPIO0_27	GPIO_RGMII2_INT#	Input	PU	Active low	Interrupt function. ('0' - interrupt pending, '1' - no interrupt) GESI - Used for PRG0_RGMII_INT#; INFO - AUDEXP_INTB

RESERVED

SERDES



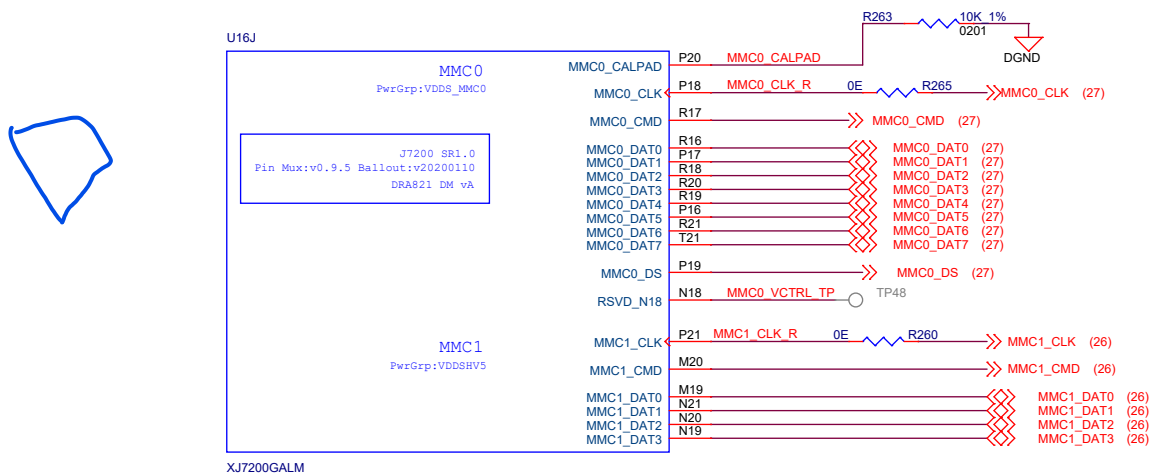
USB Type C MUX



By Pass USBC MUX	Mount - C182, C183, R237, R238, R229, R230, R234, R235 DNI - R35, R36, R37, R38, C13, C14, R16, R17
USBC MUX (Default)	Mount - R35, R36, R37, R38, C13, C14, R16, R17 DNI - C182, C183, R237, R238, R229, R230, R234, R235

MMC Interface

Via Probe Test Points



Place Near SOC

MMC0 :

MMC0_CLK_R	DNI	TP109
MMC0_DAT0	DNI	TP101
MMC0_DAT1	DNI	TP108
MMC0_DAT2	DNI	TP103
MMC0_DAT3	DNI	TP105
MMC0_DAT4	DNI	TP104
MMC0_DAT5	DNI	TP107
MMC0_DAT6	DNI	TP106
MMC0_DAT7	DNI	TP100
MMC0_DS	DNI	TP110
MMC0_CMD	DNI	TP102

MMC1 :

MMC1_CLK_R	DNI	TP111
MMC1_DAT0	DNI	TP115
MMC1_DAT1	DNI	TP114
MMC1_DAT2	DNI	TP113
MMC1_DAT3	DNI	TP112
MMC1_CMD	DNI	TP116



Project :

J7 EVM



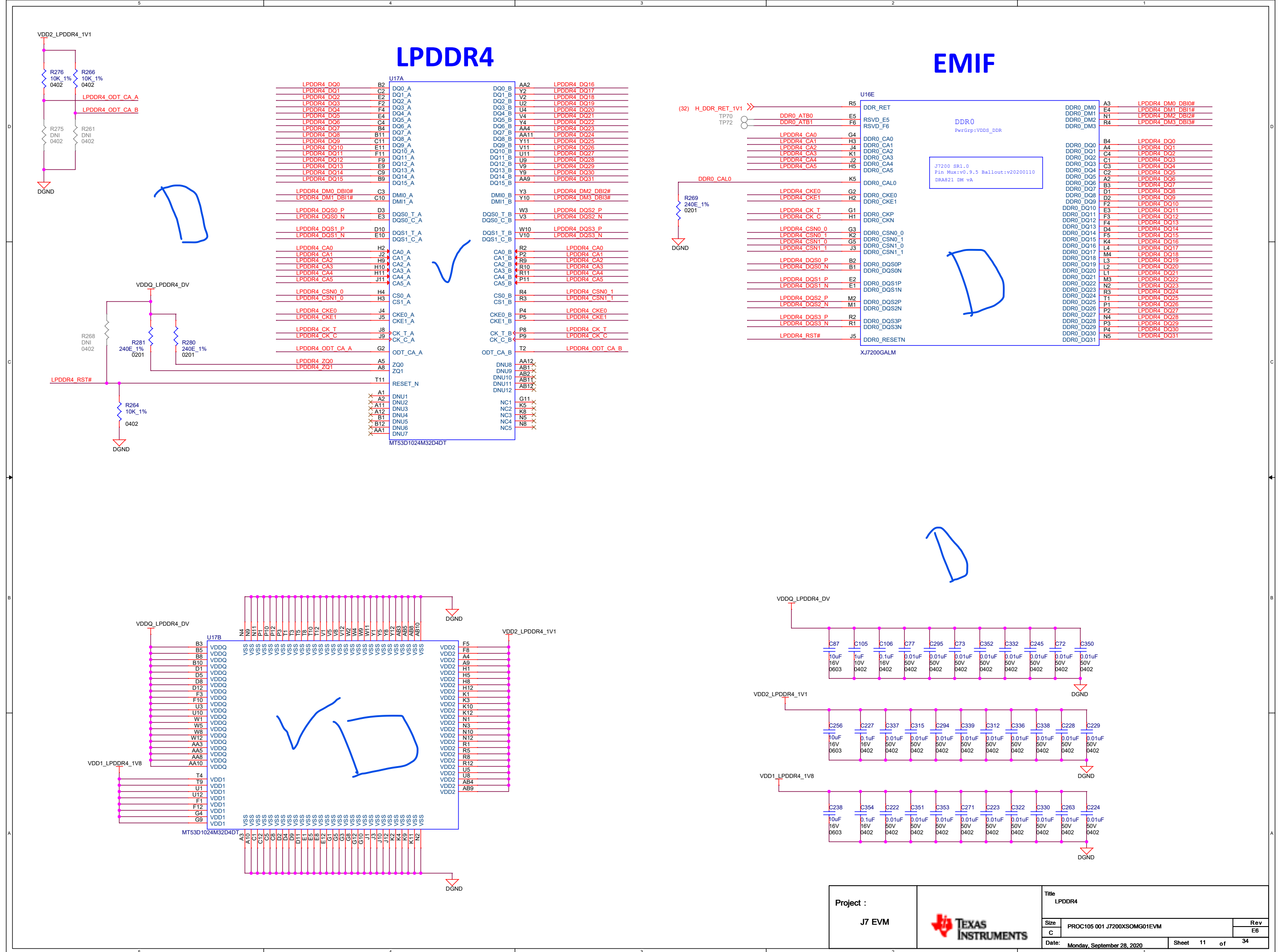
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MMC,UFS_INTERFACE

Size
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PROC105 001 J7200XSOMG01EVM

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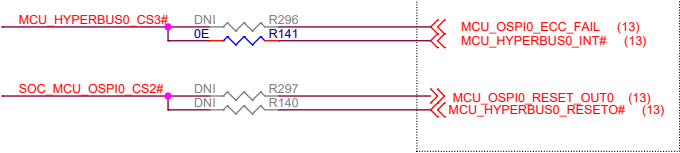
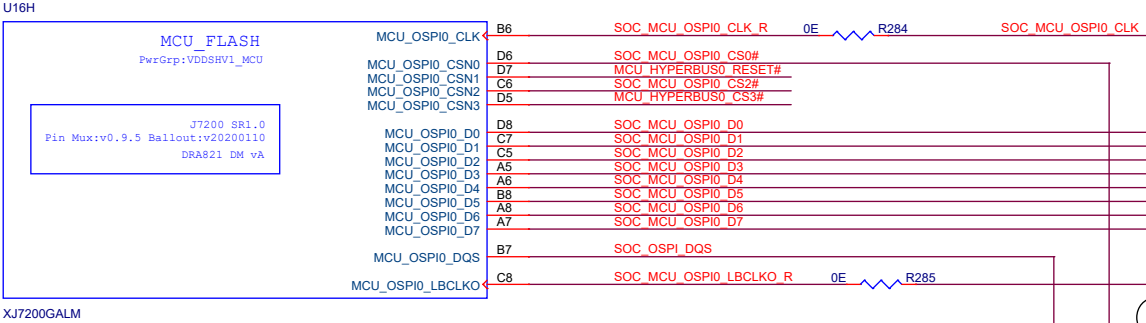
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EVM development & evaluation test circuitry
(TI EVM Only)

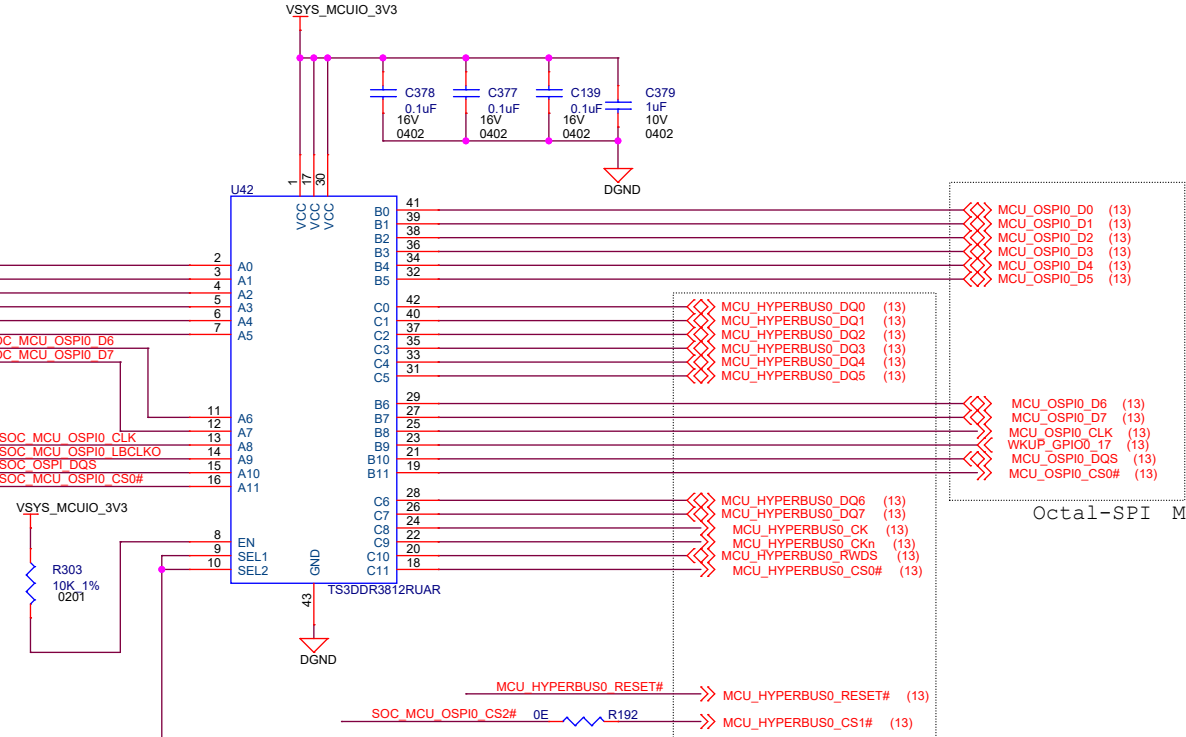
2:1 Mux for OSPI/HYBERBUS

MCU FLASH



Note: Optional OSPI/Hyperbus Signals

Route SOC_MCU_OSPI0_CLK & SOC_MCU_OSPI0_LBCLKO as differential pair



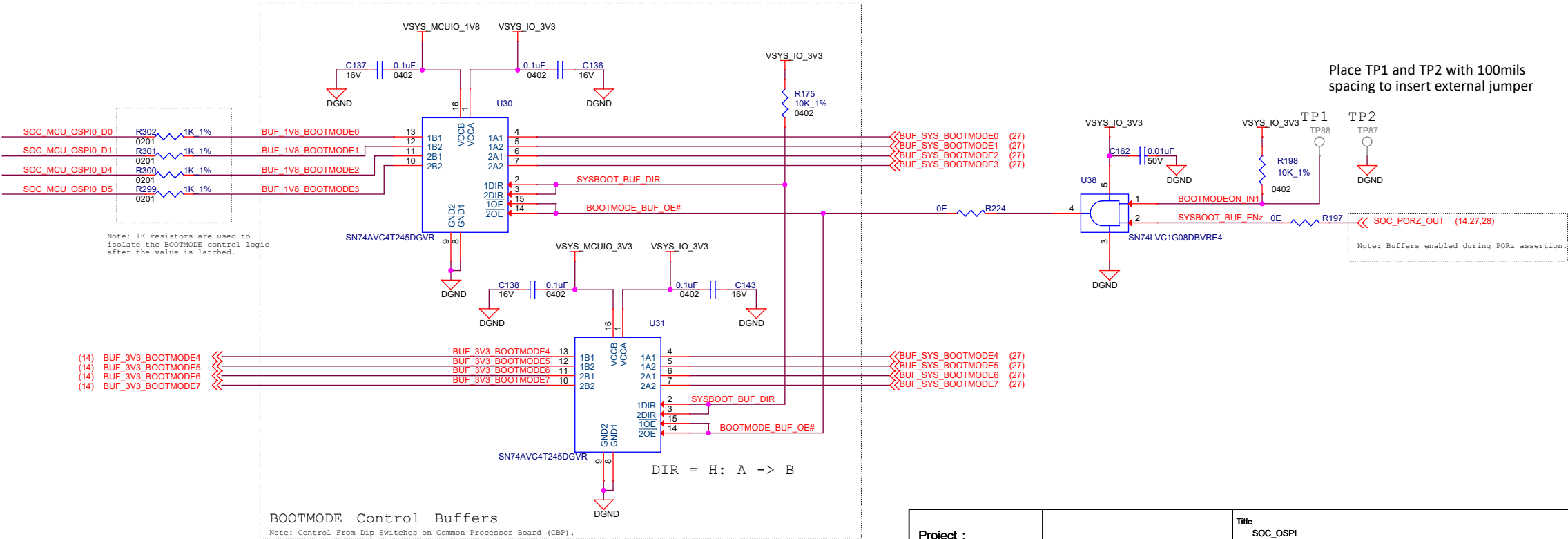
OSPI/HYPER_MUX_SEL Selection

OSPI/HYPER_MUX_SEL (14,27)

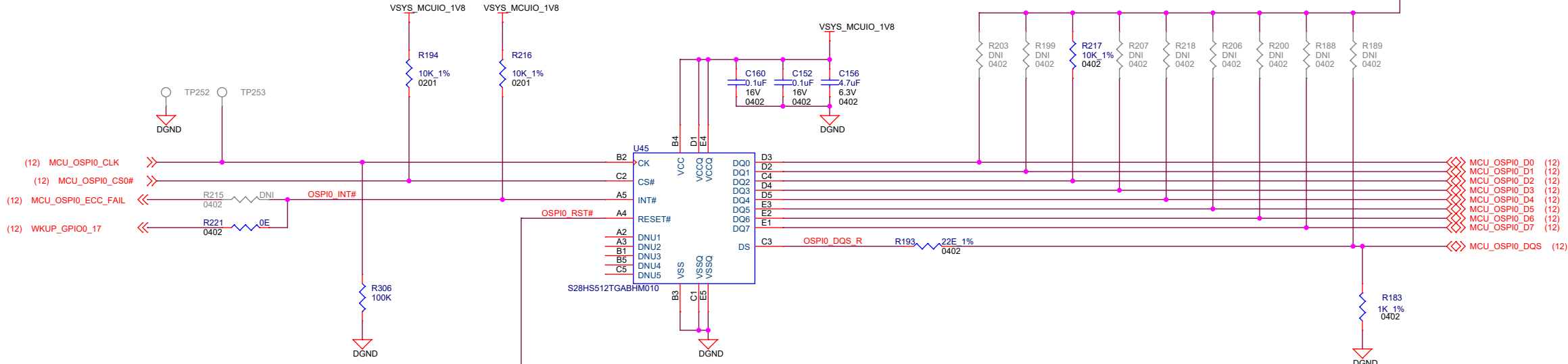
'0' - (A --> B) OSPI Flash

'1' - (A --> C) Hyperflash + HyperRAM

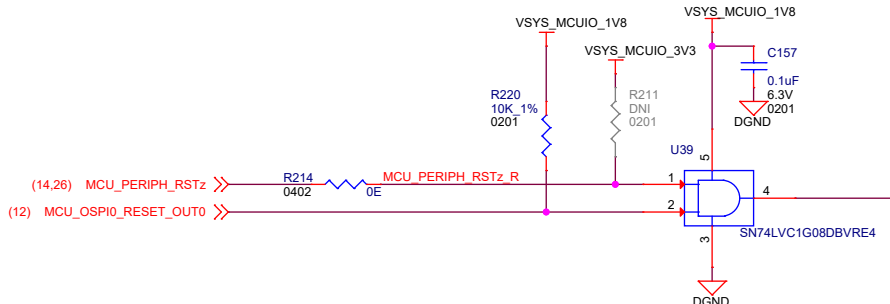
Note: Default set by dip switch



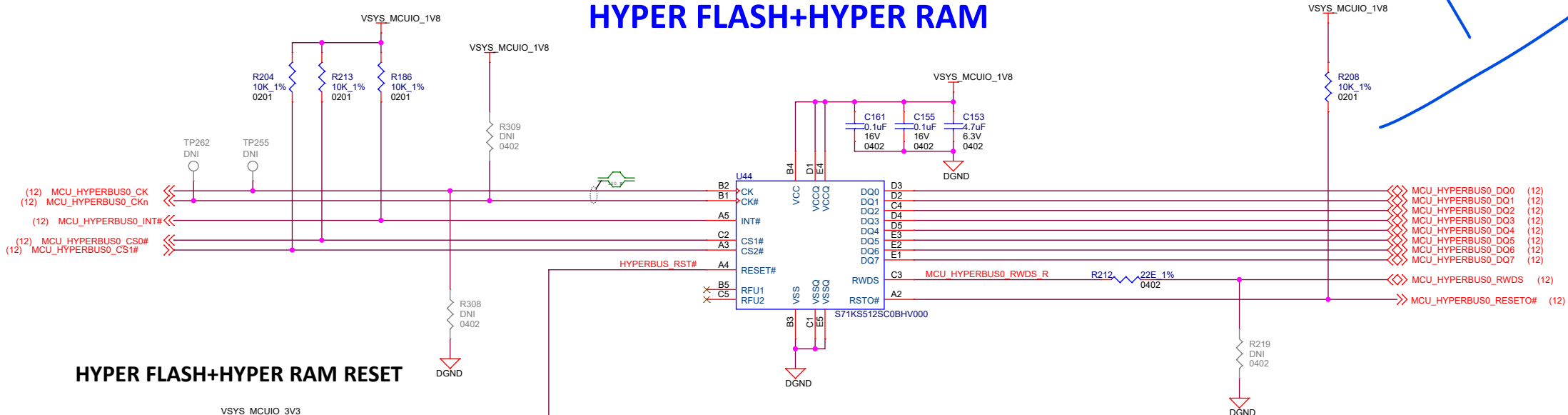
OSPI FLASH



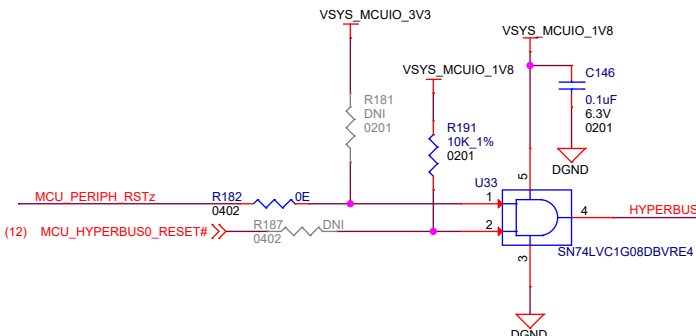
OSPI FLASH RESE



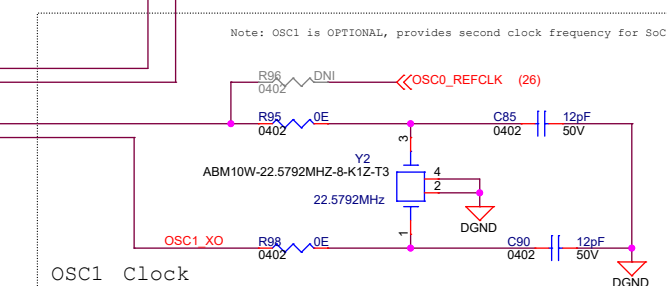
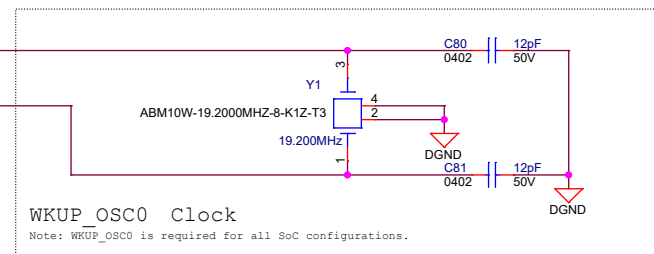
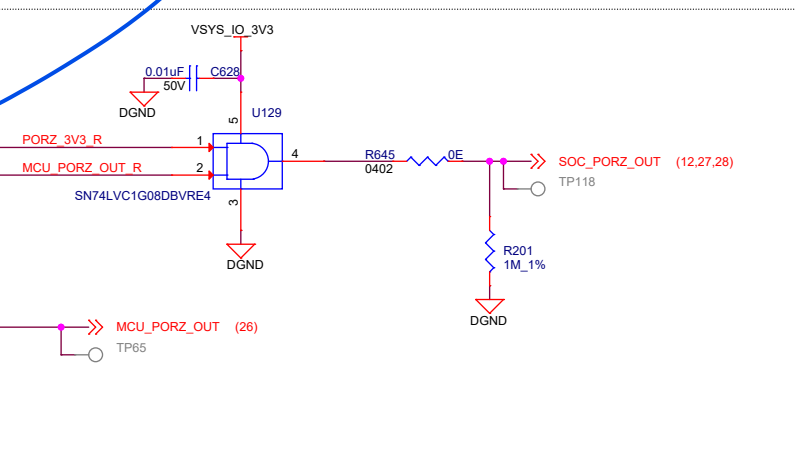
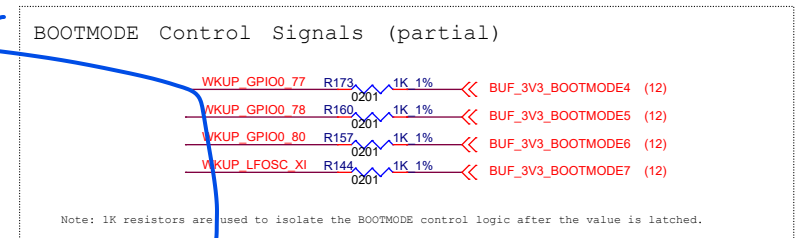
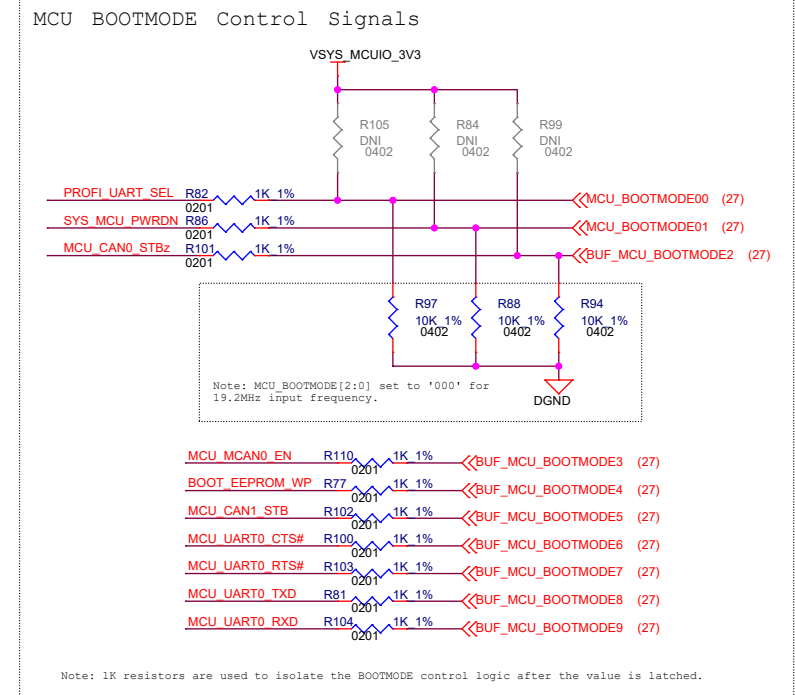
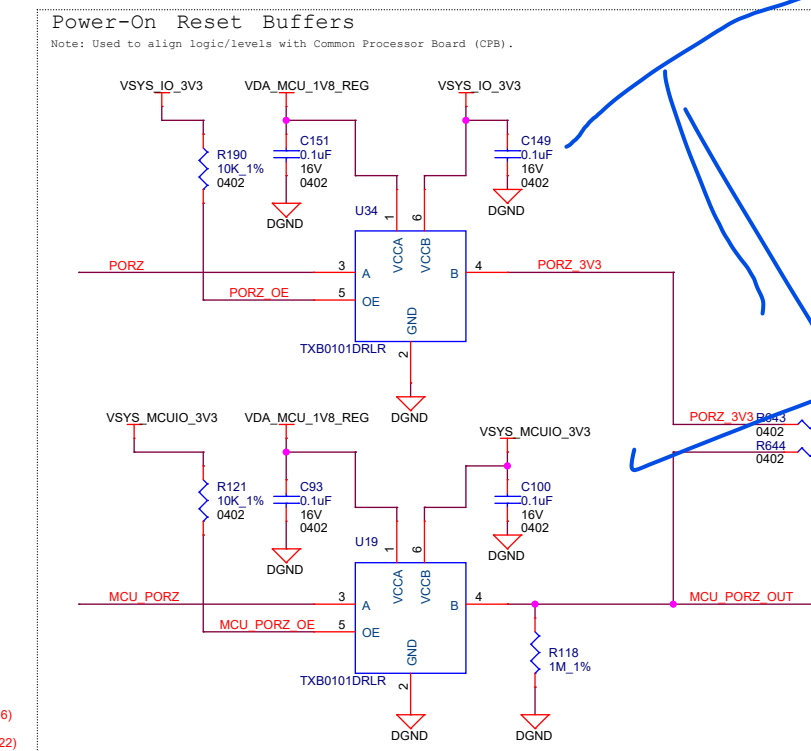
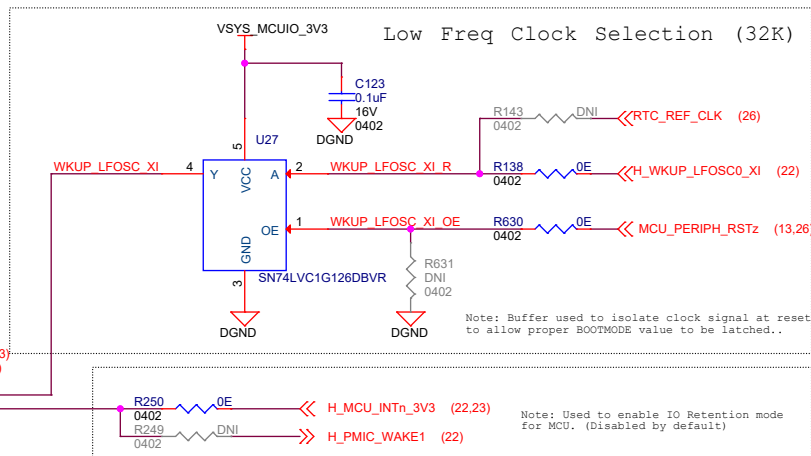
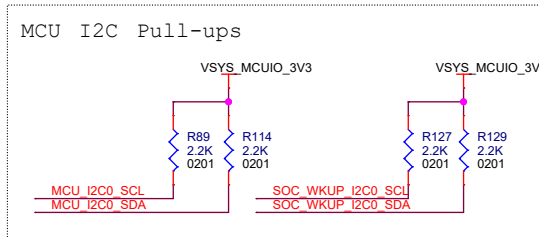
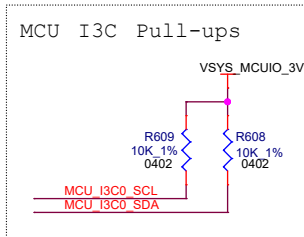
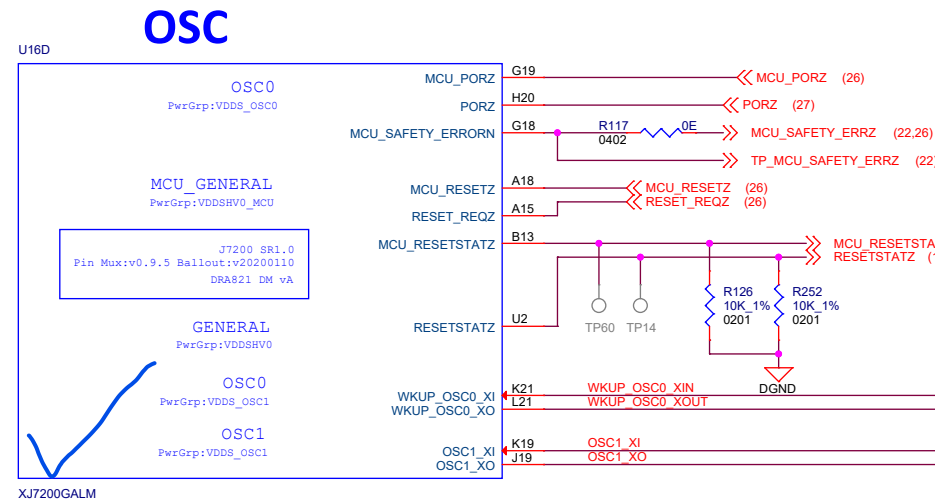
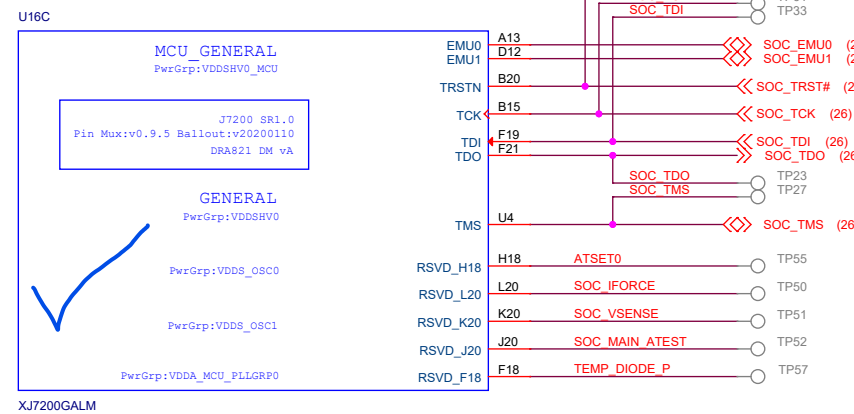
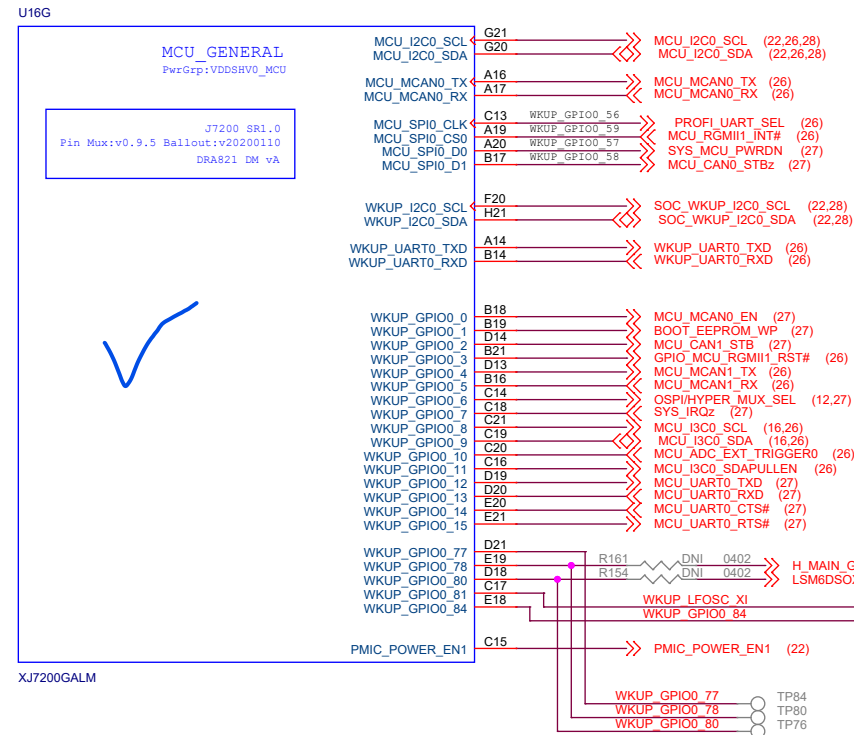
HYPER FLASH+HYPER RAM

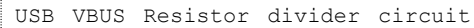
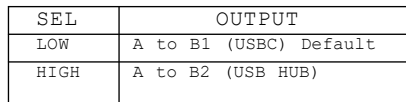


HYPER FLASH+HYPER RAM RESET

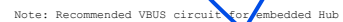


MCU & MAIN GENERAL IO, OSC CLKS





Note: Recommended VBUS circuit for USB connector. Supports 5V-30V VBUS



Project :

J7 EVM



Title	GENERAL,USB
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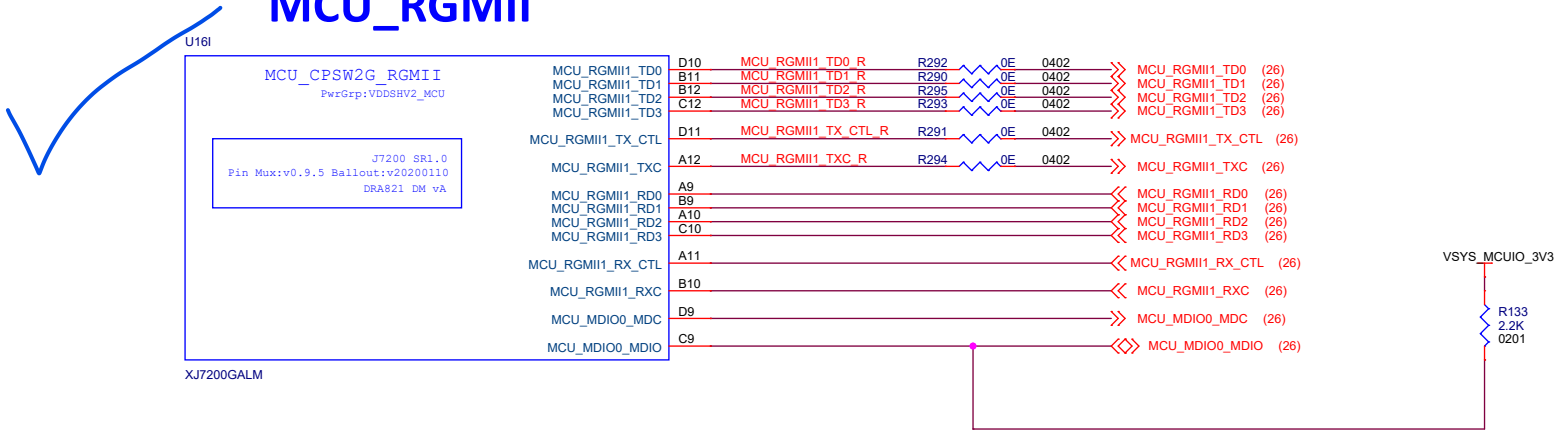
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Date:	Monday, September 28, 2020

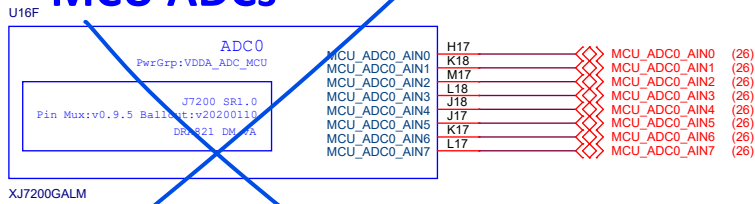
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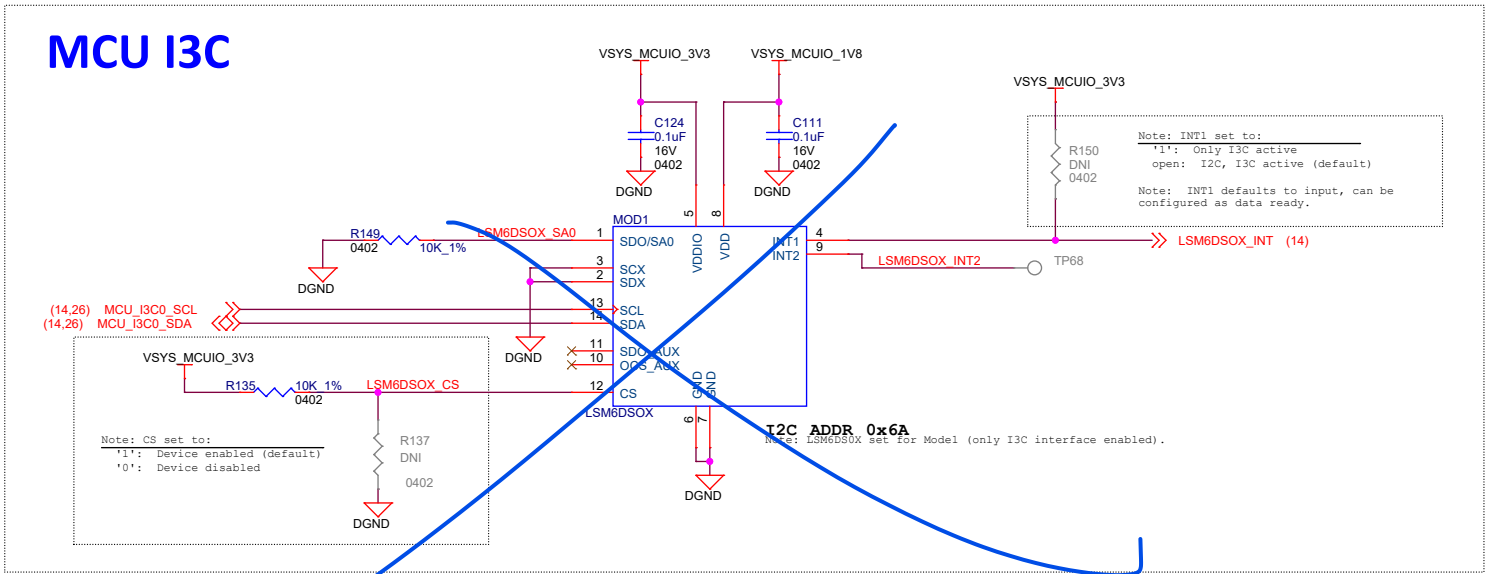
MCU_RGMII



MCU ADCs



MCU I3C



Project :

J7 EVM



Title
MCU_RGMII, MCU_ADC & MCU_I3C

Size
C PROC105 001 J7200XSOMG01EVM

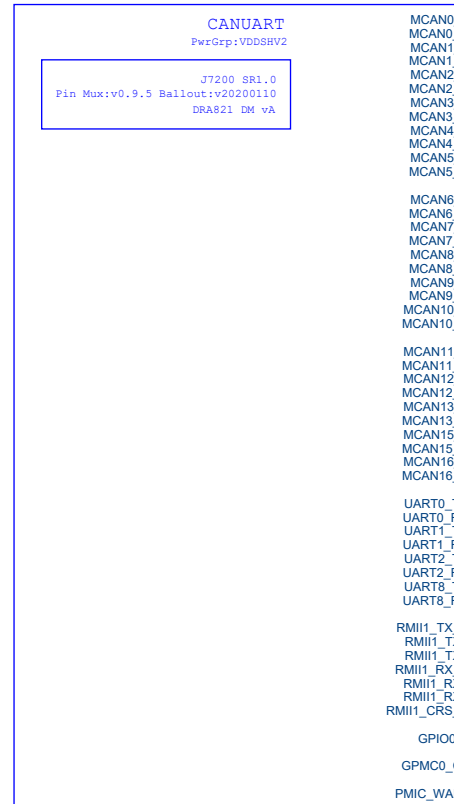
Date: Monday, September 28, 2020

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CAN/UART IO

U16K

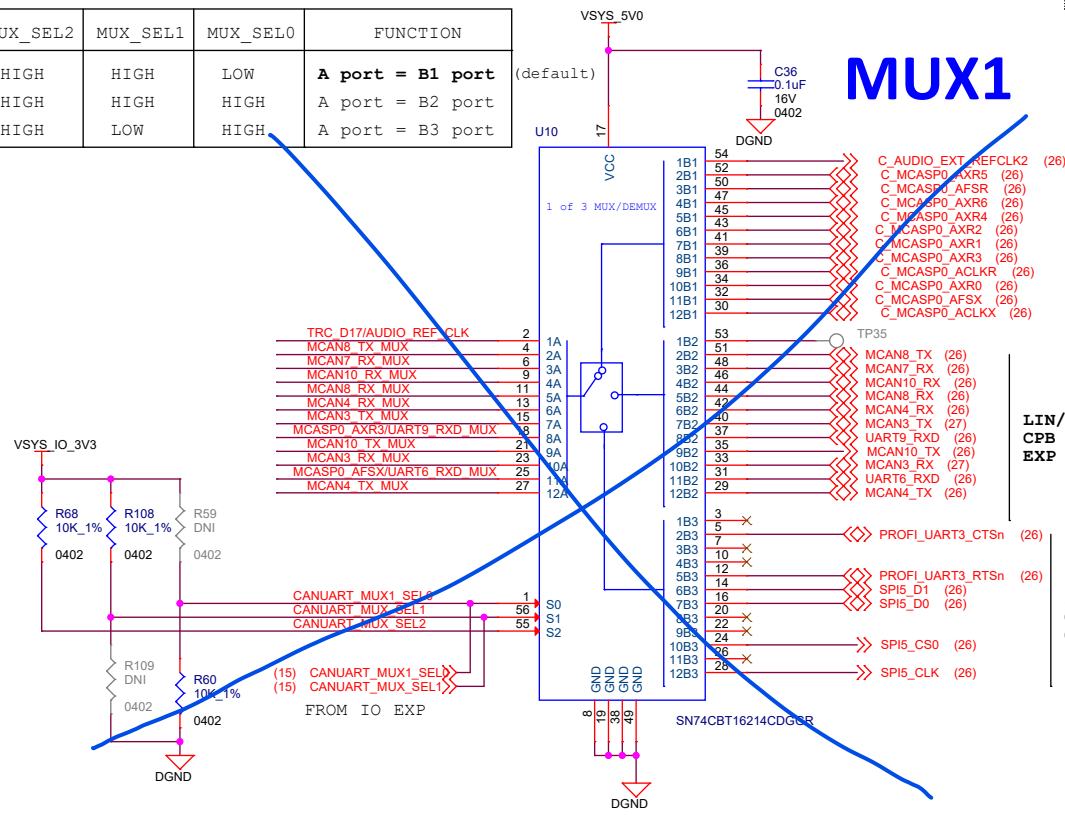


XJ7200GALM

SEL	OUTPUT
LOW	A to B1 (TRC/McASP) Default
HIGH	A to B2 (LIN/MCAN)

MCASP/TRAC/MCAN/LIN - 1:3 MUX : Truth Table

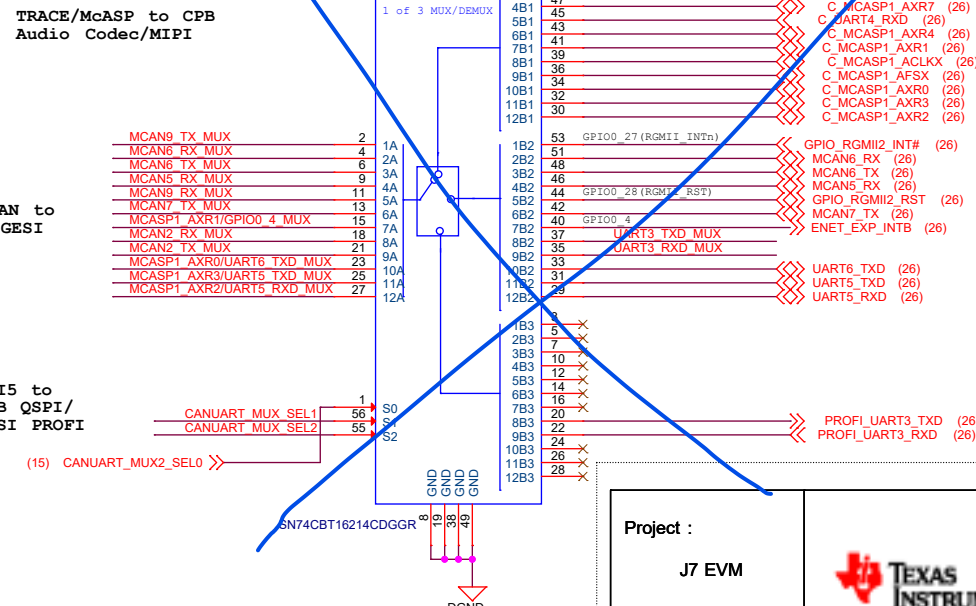
MUX_SEL2	MUX_SEL1	MUX_SEL0	FUNCTION
HIGH	HIGH	LOW	A port = B1 port
HIGH	HIGH	HIGH	A port = B2 port
HIGH	LOW	HIGH	A port = B3 port



TRACE/McASP to CPB
Audio Codec/MIPI

LIN/MCAN to
CPB & GESI
EXP

SPI5 to
CPB QSPI/
GESI PROF1



SoC to Common Processor Board (CPB) Pin Mux

Note: Mux to align pin multiplexing between SoC and Common Processor Board (CPB).

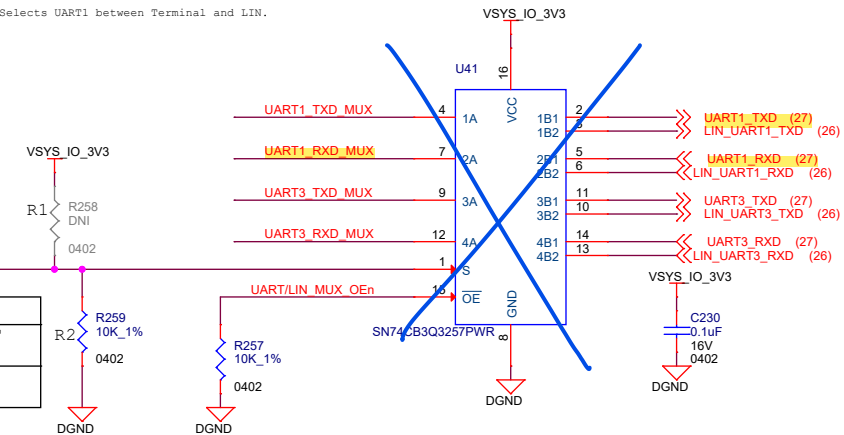
TRACE/McASP to CPB
FPD Tuner/MIPI

To CPB-EXP
LIN/CAN

GESI PROF1

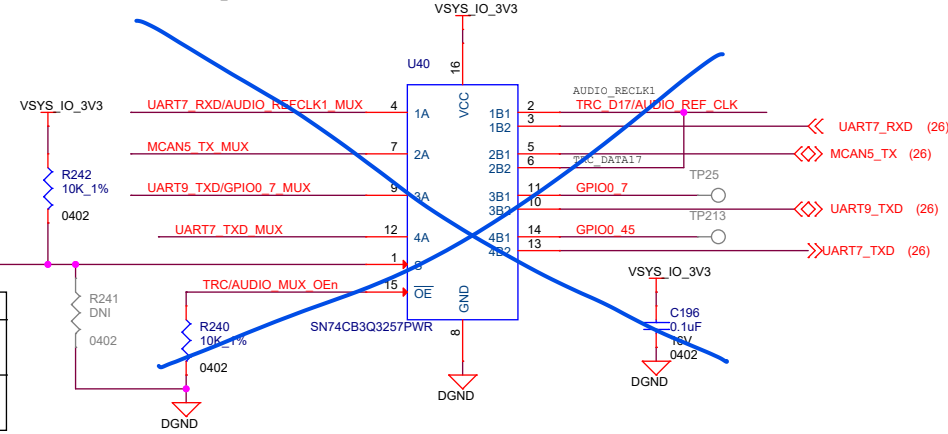
UART1 Mux

Note: Selects UART1 between Terminal and LIN.



SoC to Common Processor Board (CPB) Pin Mux

Note: Mux to align pin multiplexing between SoC and Common Processor Board (CPB).
(Specifically new location of AUDIO_REFCLK)



SEL	OUTPUT
LOW	A to B1 (Audio_refclk/ MCAN5_TX/GPIO0_7)
HIGH	A to B2 (UART7_RXD/UART7_TXD/ TRC D17/UART9_TXD)

Project :

J7 EVM



Title

CANUART

Size

PROC105 001 J7200XSOMG01EVM

C

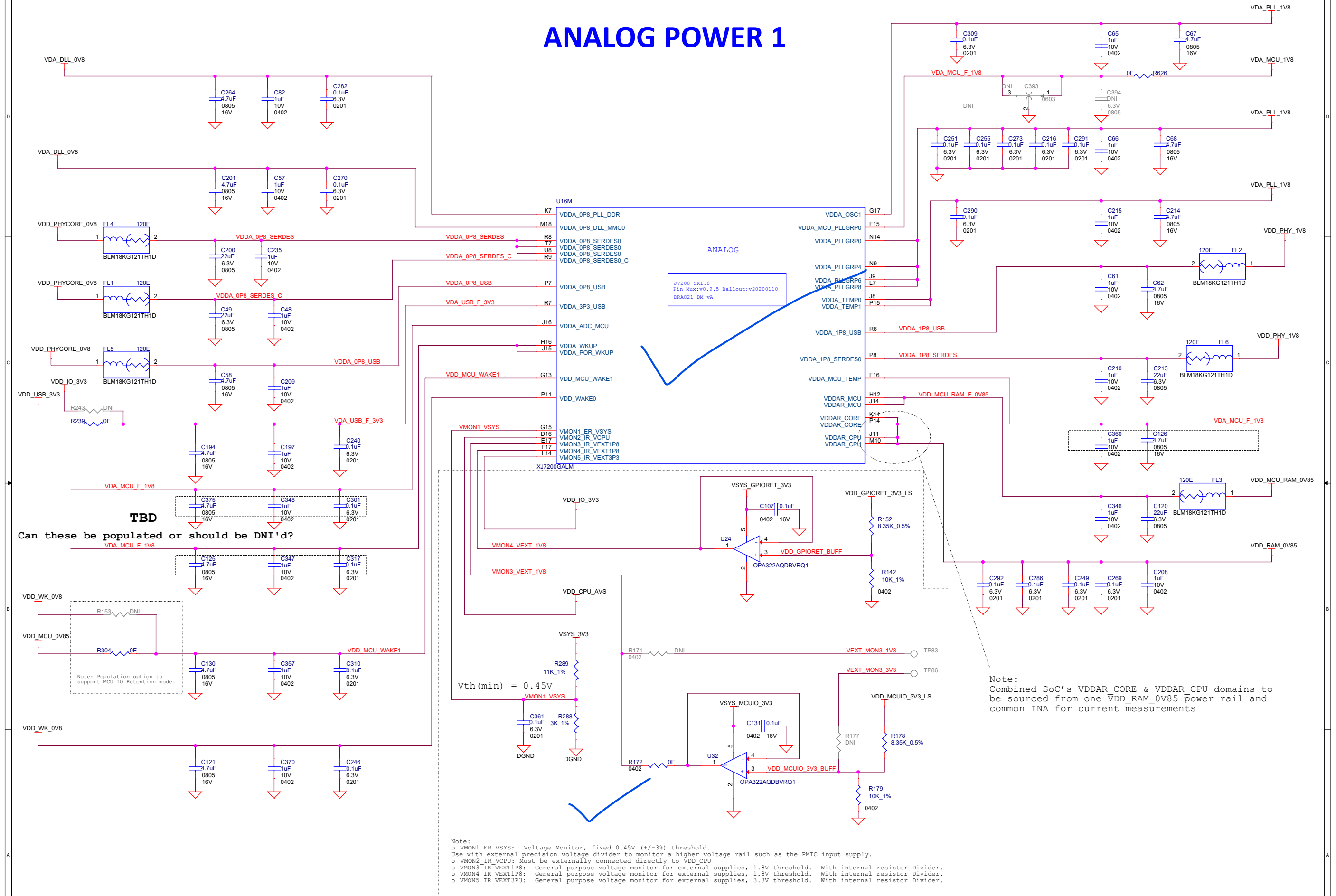
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ANALOG POWER 1



Note:
Combined SoC's VDDAR CORE & VDDAR CPU domains to be sourced from one VDD_RAM_0V85 power rail and common INA for current measurements

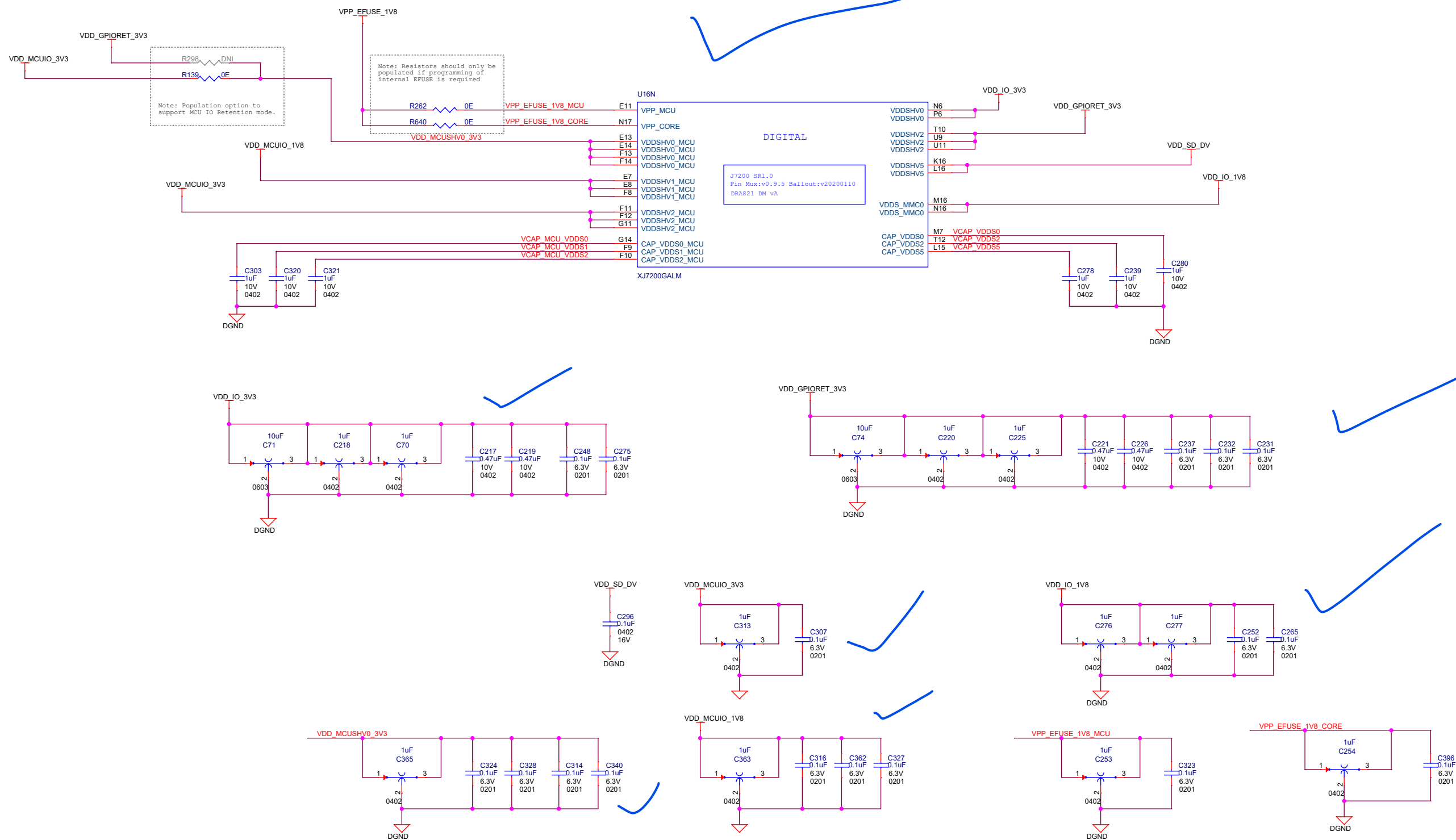
Note:

- o VM0N1_ER_VSYS: Voltage Monitor, fixed 0.45V (+/-3%) threshold.

Use with external precision voltage divider to monitor a higher voltage rail such as the PMIC input supply.

- o VM0N2_IR_VCPU: Must be externally connected directly to VDD_CPU
- o VM0N3_IR_VEXT1P3: General purpose voltage monitor for external supplies, 1.8V threshold. With internal resistor Divider
- o VM0N4_IR_VEXT1P8: General purpose voltage monitor for external supplies, 1.8V threshold. With internal resistor Divider
- o VM0N5_IR_VEXT3P3: General purpose voltage monitor for external supplies, 3.3V threshold. With internal resistor Divider

DIGITAL POWER 2



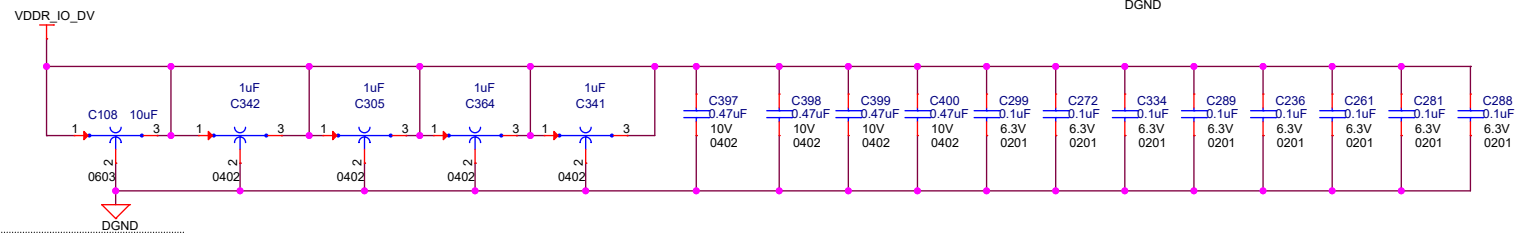
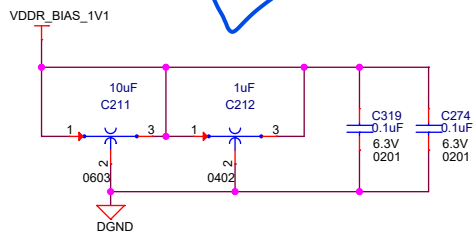
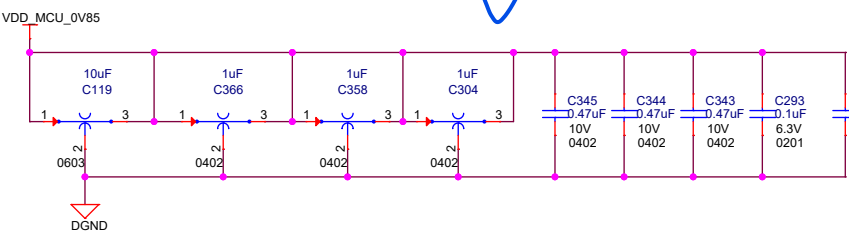
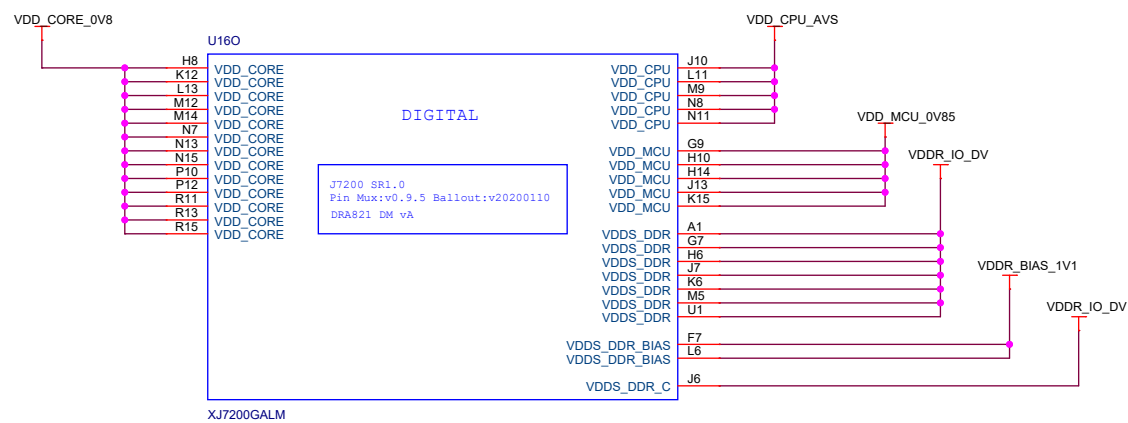
Note:

A few Dcaps shown here have been provisioned on PCB layout underneath SoC at individual power ball vias & around perimeter in case additional high-freq decoupling might be needed.

Some Dcaps may be shown as "Do Not Install" (DNI) components if Power Integrity (PI) simulation results for a particular power rail on this EVM PCB design combined with Dcap scheme (value, pkg type, ESL, Loop-Inductance, etc.) results in an impedance response below or equal to the desired target impedance (Z_t).

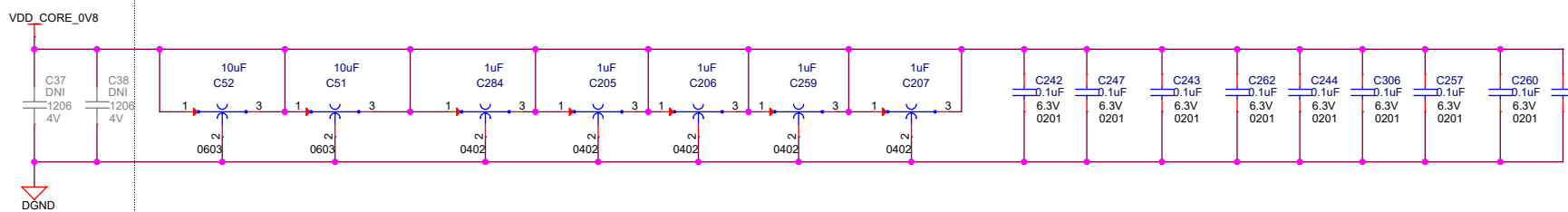
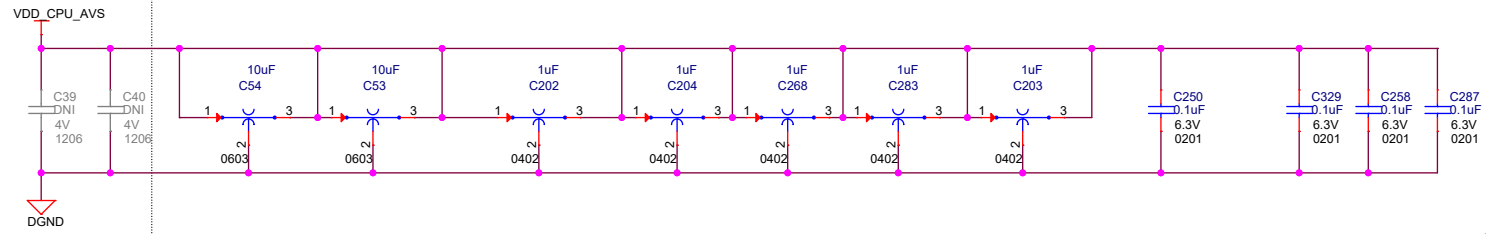
Project : J7 EVM		Title SOC POWER 2			
		Size	PROC105 001 J7200XSOMG01EVM	Rev	
		C		E6	
		Date:	Monday, September 28, 2020	Sheet	19

DIGITAL POWER 3



Note:

These can be used for power distribution optimizations



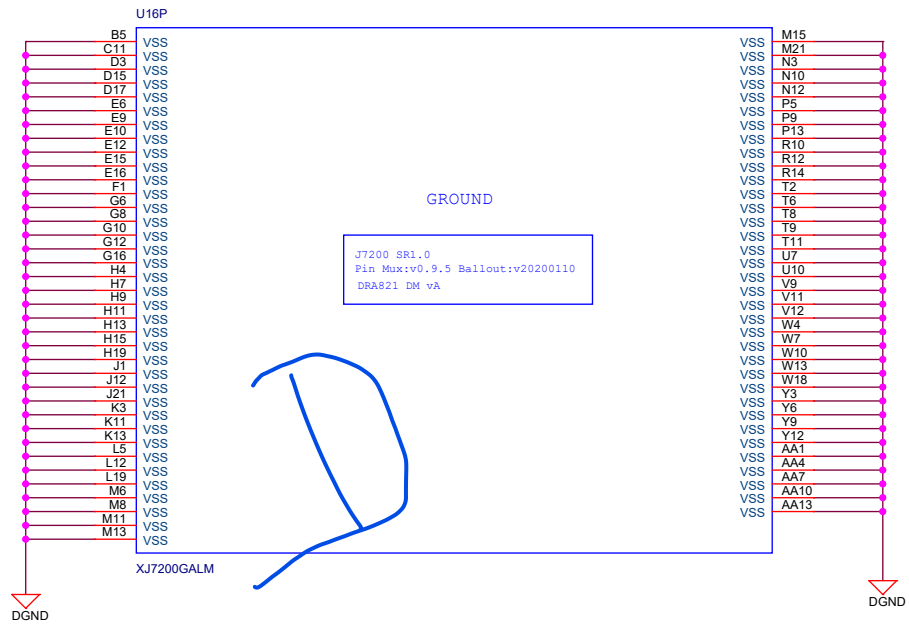
Note:

A few Dcaps shown here have been provisioned on PCB layout underneath SoC at individual power ball vias & around perimeter in case additional high-freq decoupling might be needed.

Some Dcaps may be shown as "Do Not Install" (DNI) components if Power Integrity (PI) simulation results for a particular power rail on this EVM PCB design combined with Dcap scheme (value, pkg type, ESL, Loop-Inductance, etc.) results in an impedance response below or equal to the desired target impedance (Z_t).

Project : J7 EVM		Title SOC POWER 3	
		Size C	Rev E6
		Date: Monday, September 28, 2020 Sheet 20 of 34	

SOC GROUND

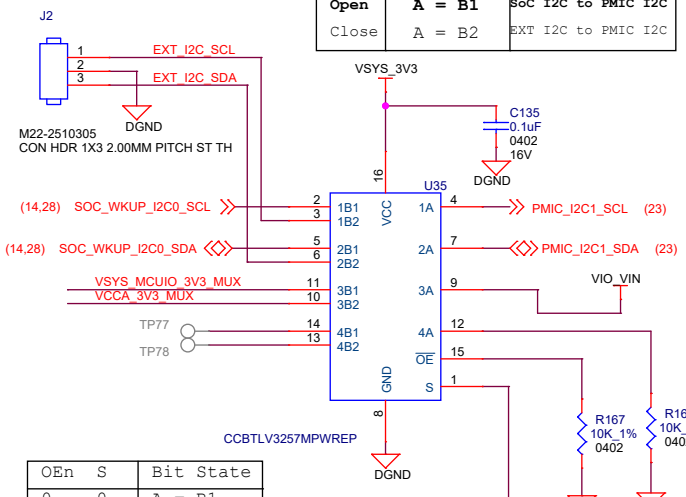


EVM development & evaluation Test circuitry

(TI EVM Only)

(EVM Bd Default Setting):

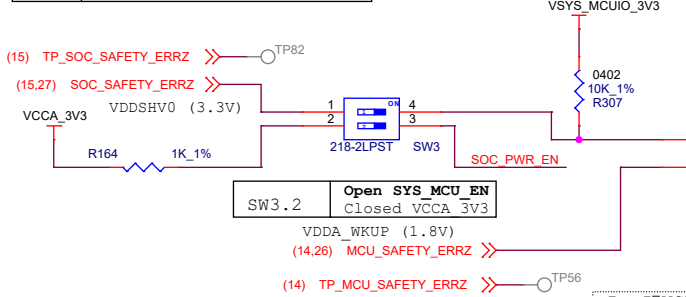
SW4.2	Port State	Function
Open	A = B1	SoC I2C to PMIC I2C
Close	A = B2	EXT I2C to PMIC I2C



OEn	S	Bit State
0	0	A = B1
0	1	A = B2
1	X	Open

(EVM Bd Setting & Leo NVM Default):

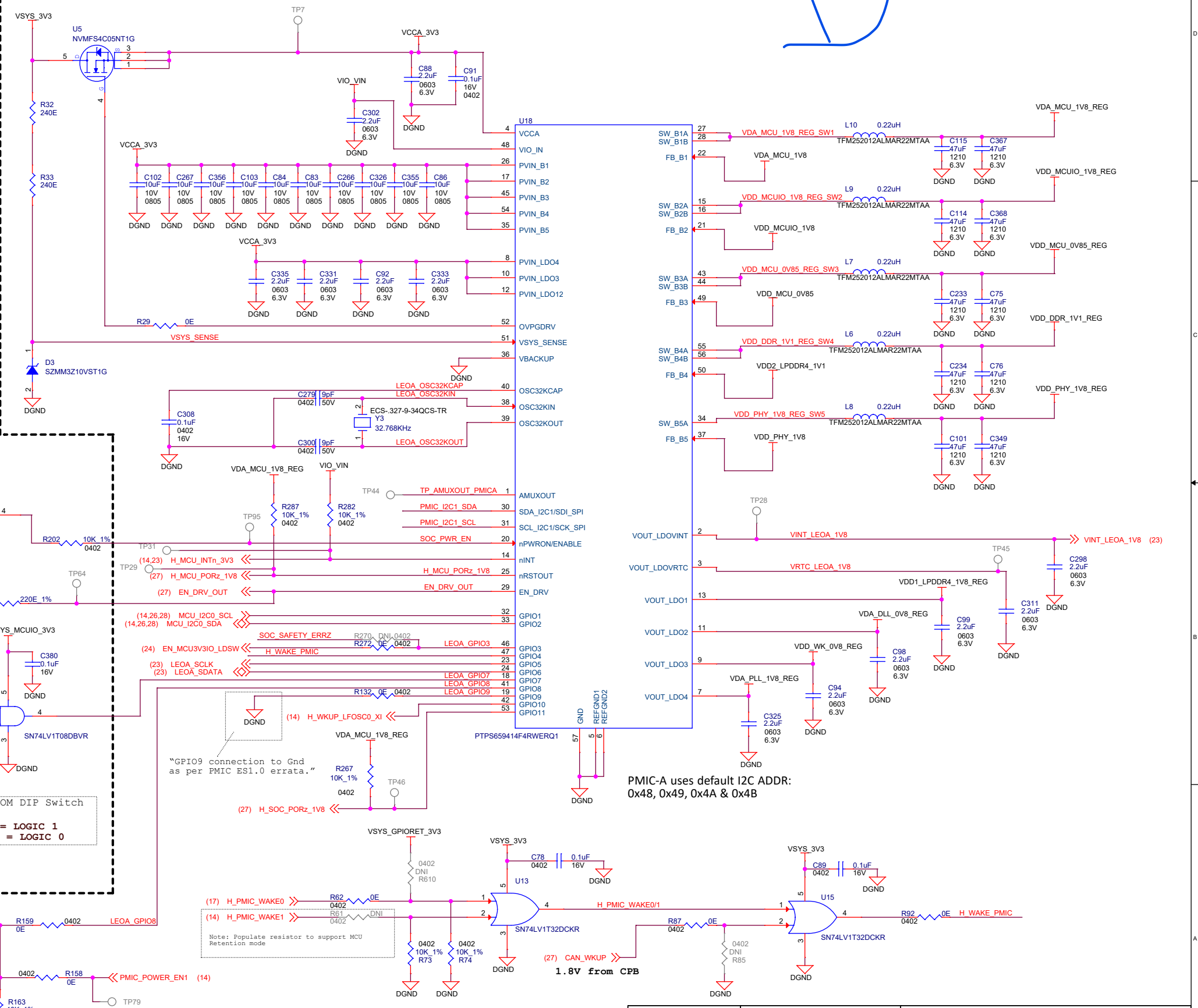
SW3.1	SYS SAFETY ERRn
Open	MCU SAFETY_ERRn
Closed	Active low, SoC ERRn or MCU ERRn



(EVM Bd Setting & Leo NVM Default):

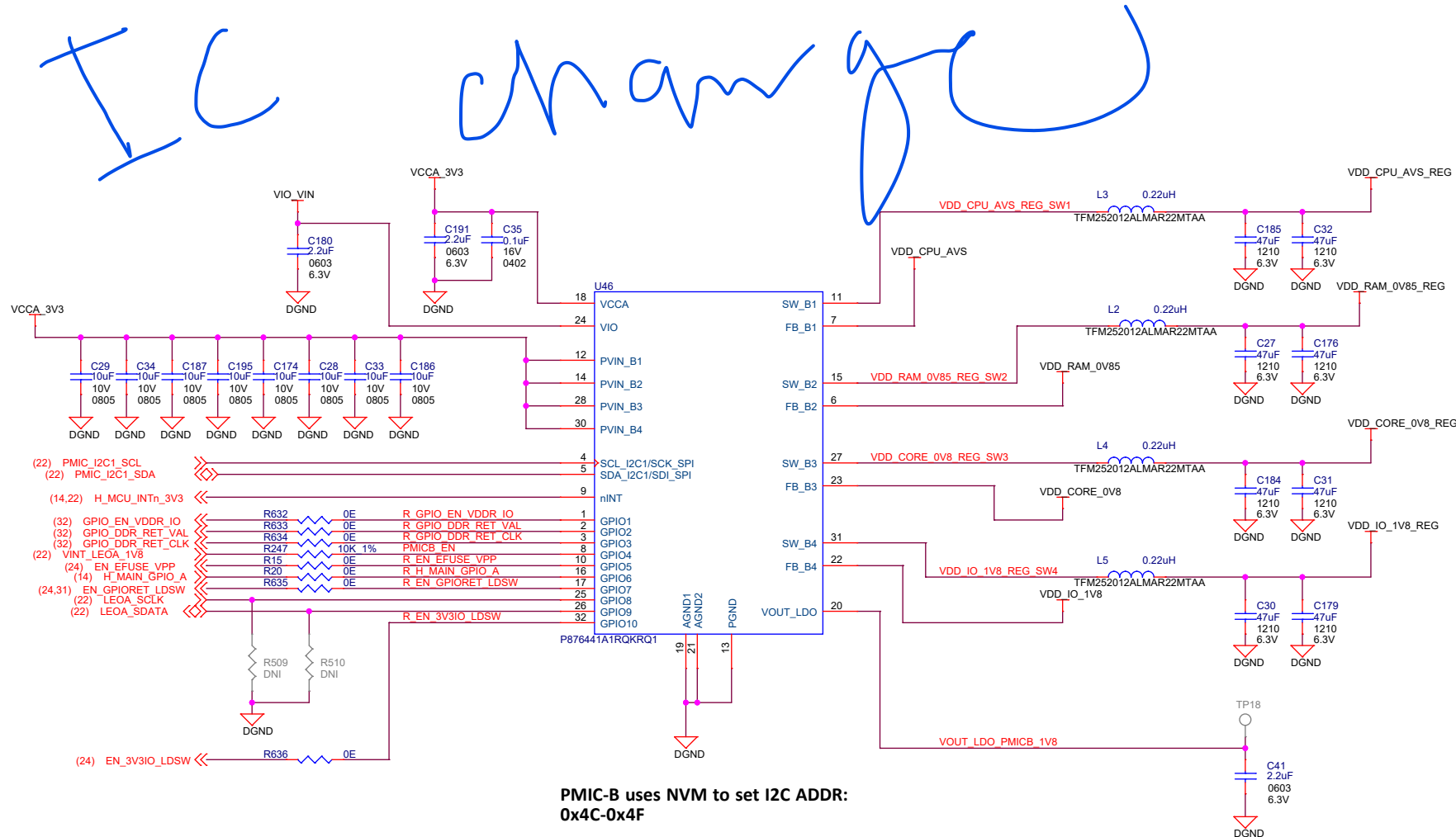
SW2		GPIO: Type	NVM Funtion
-1 = Open (Low) = Closed (High)	NA	NA	NA
-2 = Closed (High) = Open (Low)	Disable WDOG Timer Enable WDOG Timer	In In	Disable WDOG Enable WDOG

PMIC- A



PMIC-A uses default I2C ADDR:
0x48, 0x49, 0x4A & 0x4B

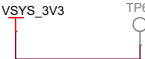
PMIC - B



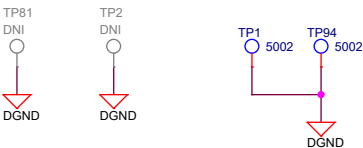
- "PCB Notes:
- For single-phase Buck converters, route remote sense feedback as follows:
 - Single-ended traces on same layer & next to primarily power plane segment as best as possible. Avoid routing near to any noisy/switching signals.
 - Connect each trace, as close as possible, to a power via near in middle of SOC power ball group.
 - Trace widths = 4-8mil"

PMIC-B uses NVM to set I2C ADDR:
0x4C-0x4F

Power Test Point

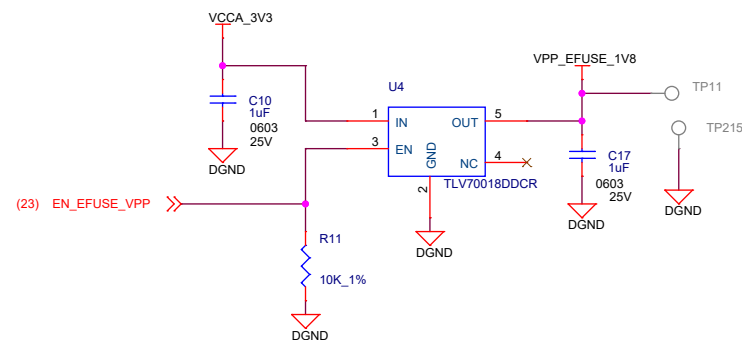
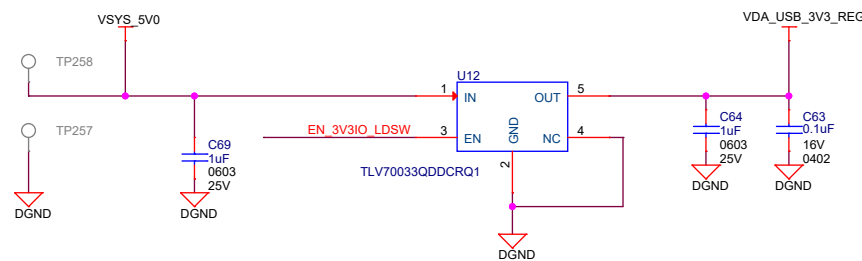
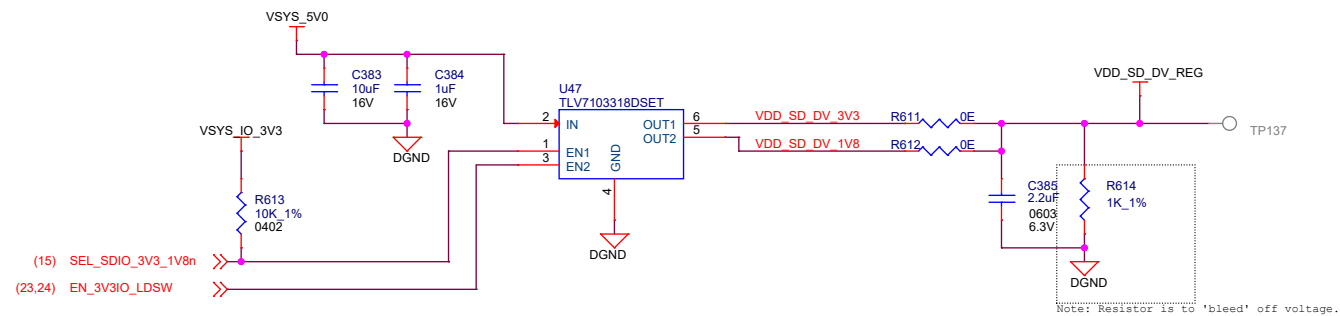
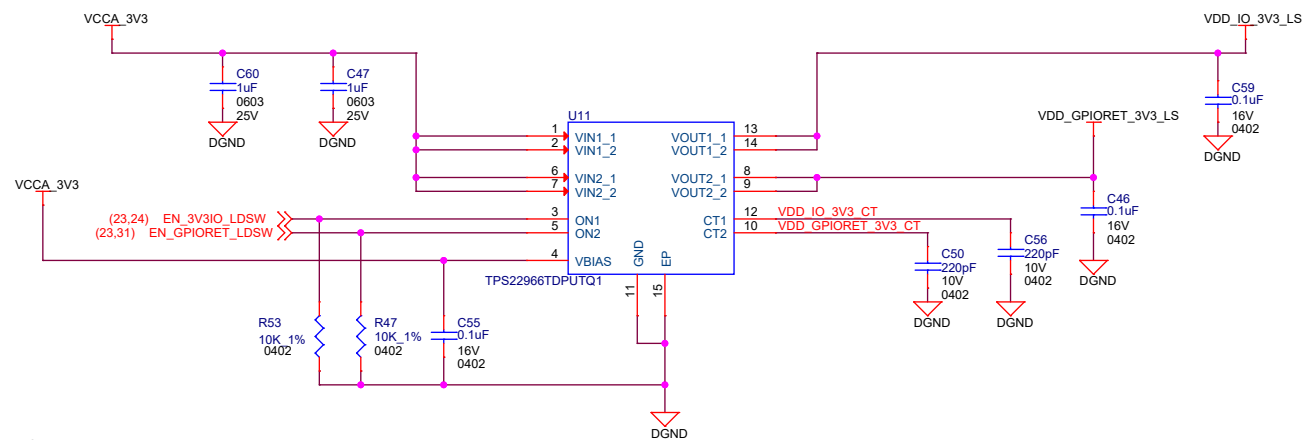
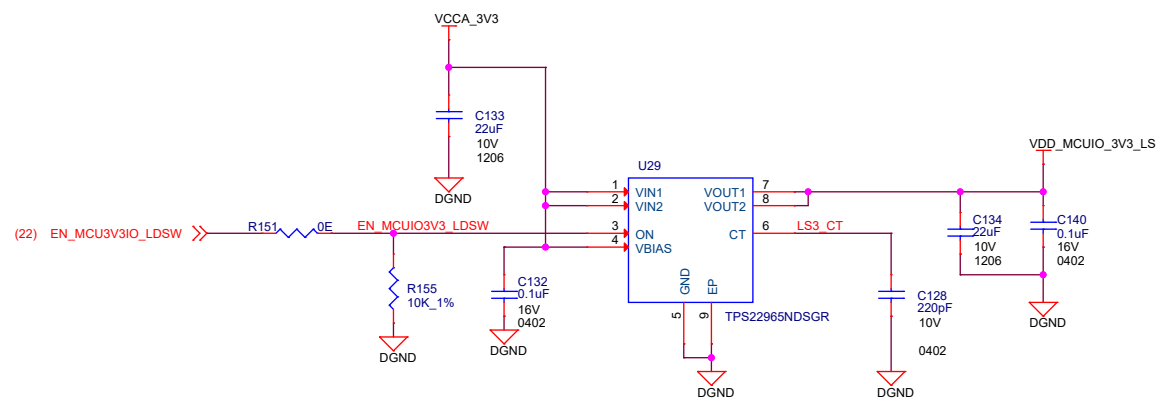


Ground Test Points

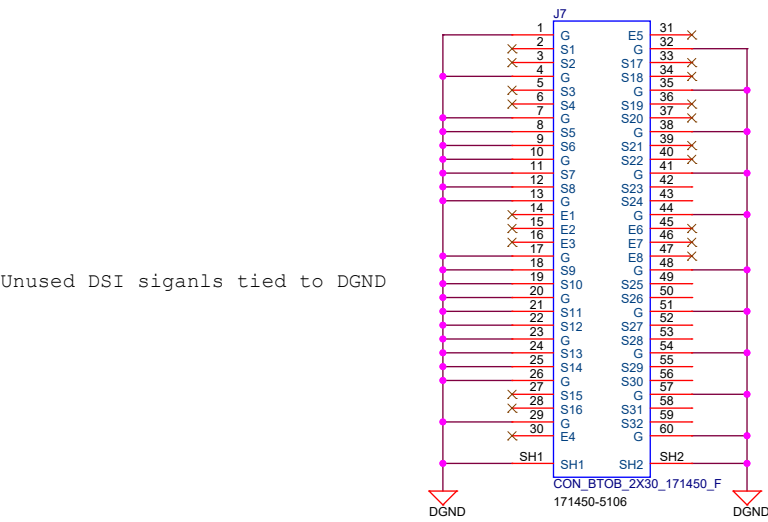
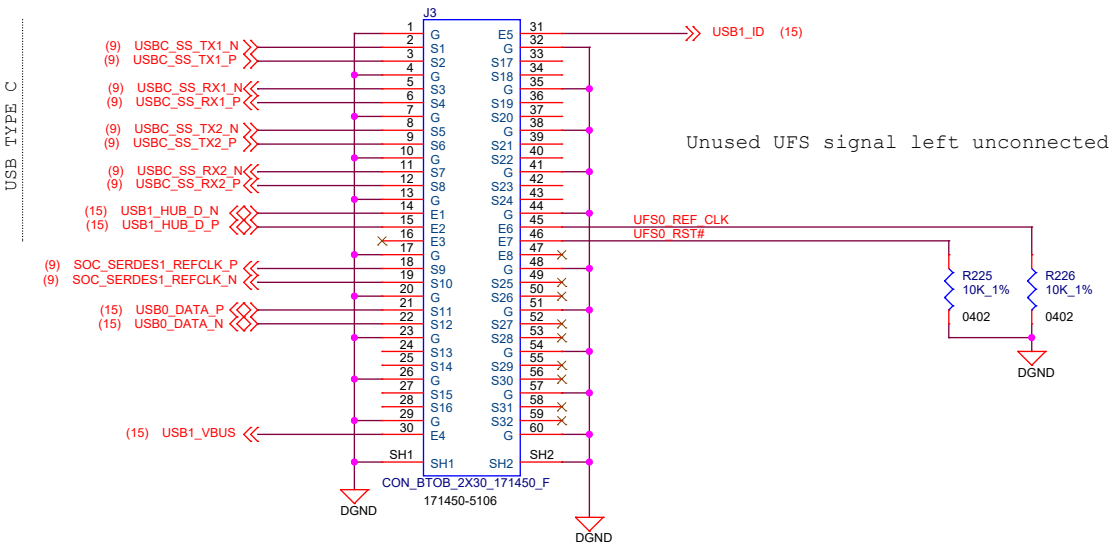
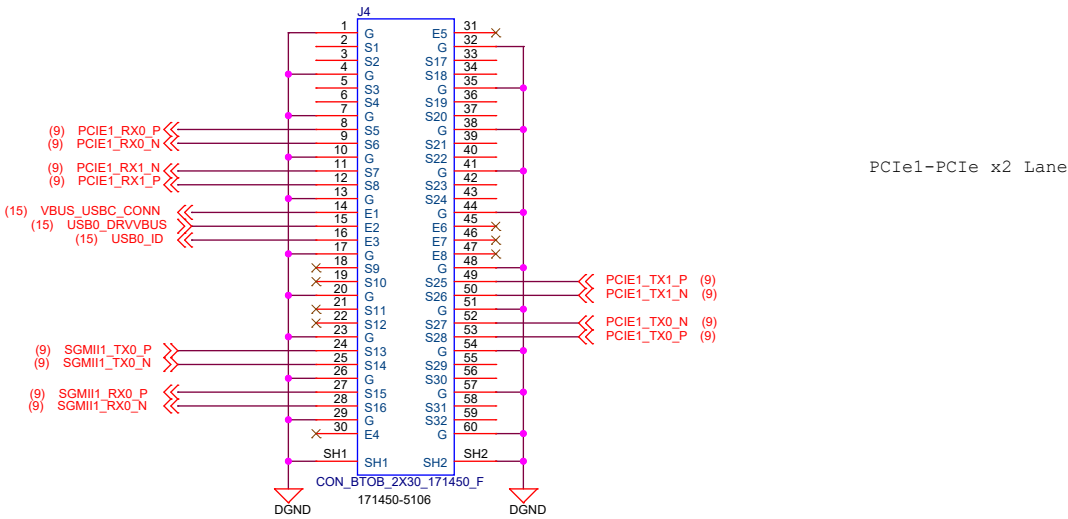


Project : J7 EVM		Title POWER SUPPLY 2	
Size C		PROC105 001 J7200XSOMG01EVM	Rev E6
Date: Monday, September 28, 2020		Sheet 23 of 34	

LOAD SWITCHES



SOM to COMM PROC SERDES CONNECTORS



SOM to COMM PROC PRIMARY CONN #1



Project :

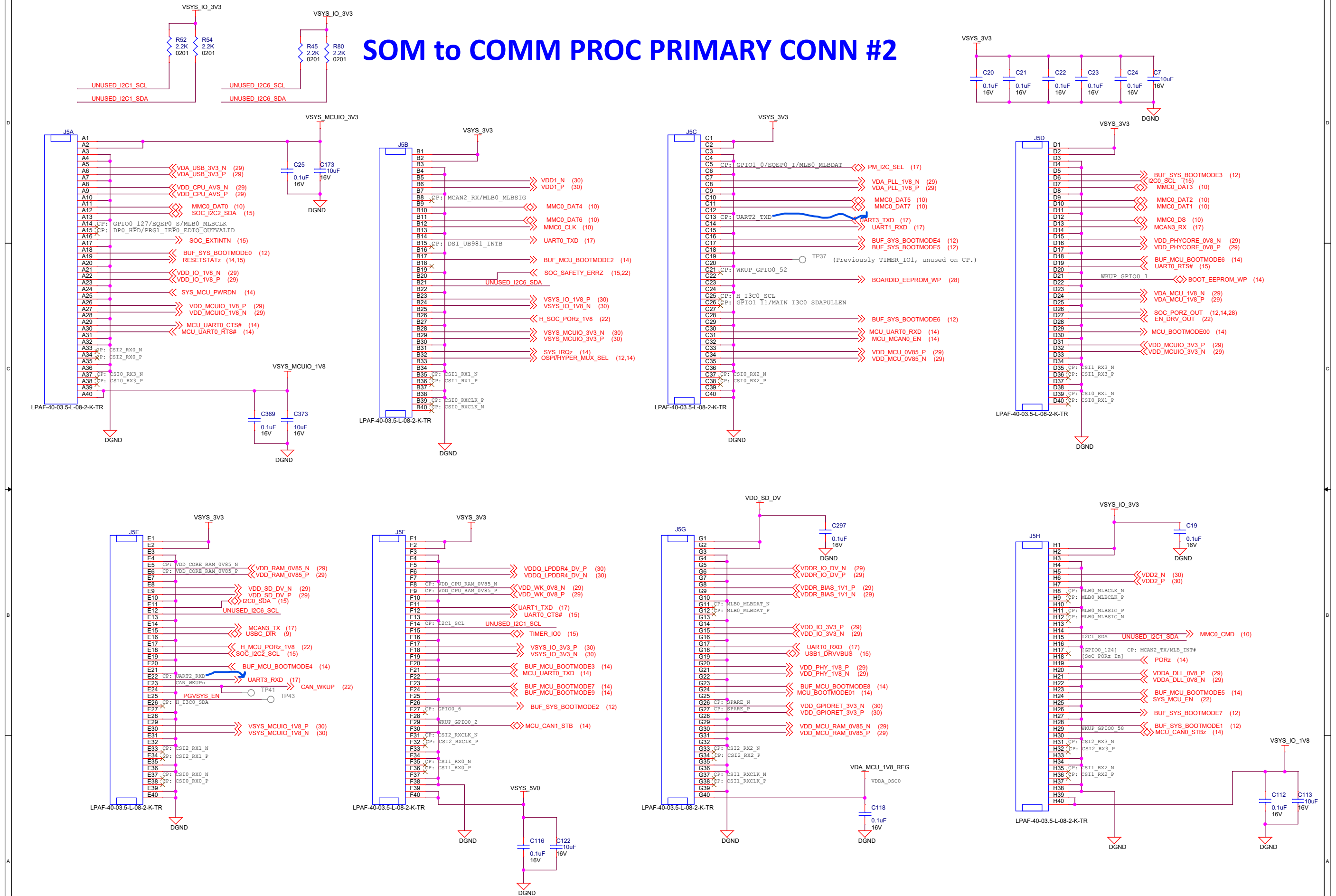
J7 EVM



Title	SOM B-B SAMTEC CONN#1
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Size	PROC105 001 J7200XSOMG01EVM	Rev
C		E6
Date:	Monday, August 24, 2020	Sheet 26 of 34

SOM to COMM PROC PRIMARY CONN #2



Project : J7 EVM



Title	SOM B-B SAMTEC CONN#2
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Size	PROC105 001 J7200XSOMG01EVM
C	

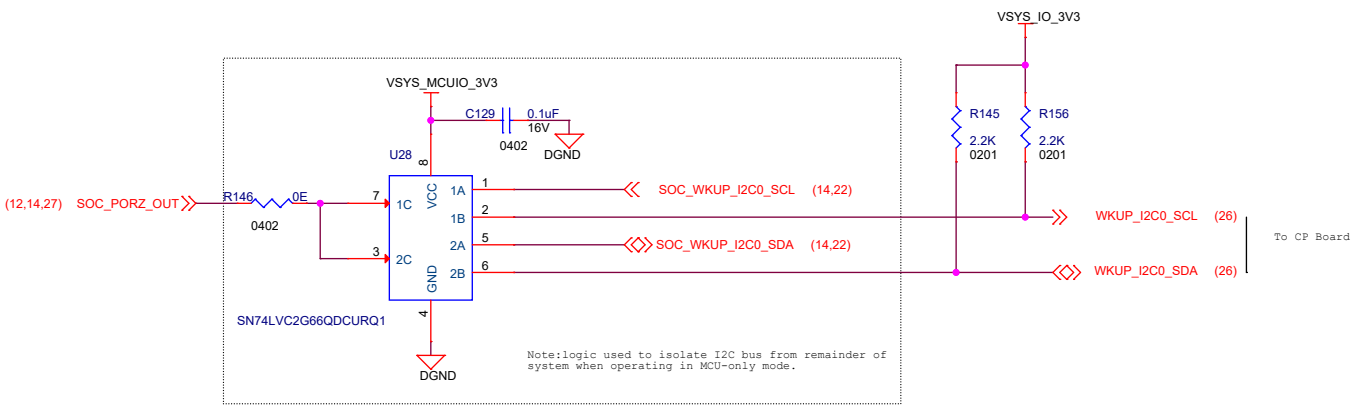
Date: Monday, September 28, 2020

Rev
E6

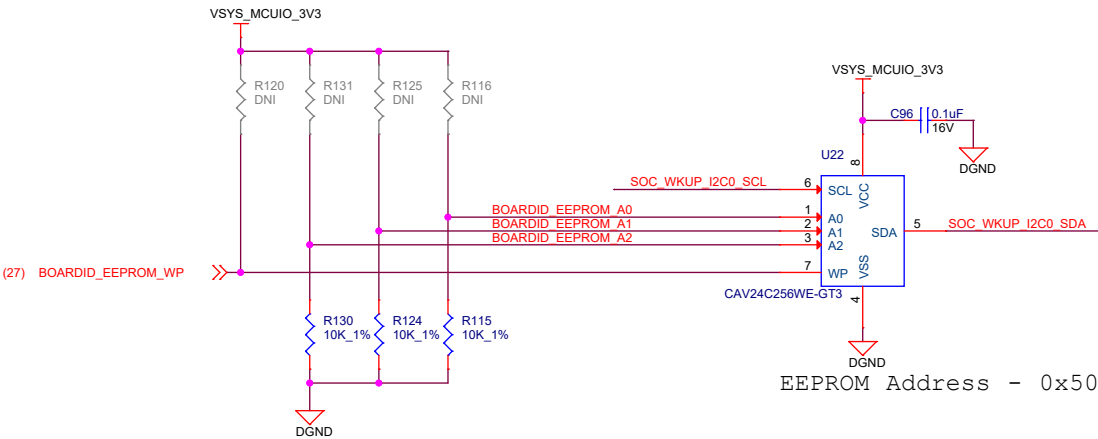
Sheet	27	of	34
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EVM development & evaluation test circuitry
(TI EVM Only)

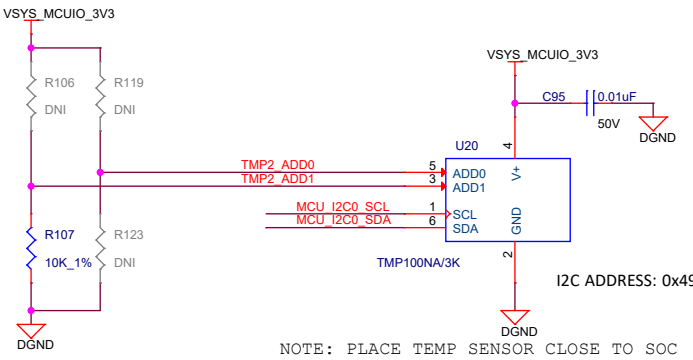
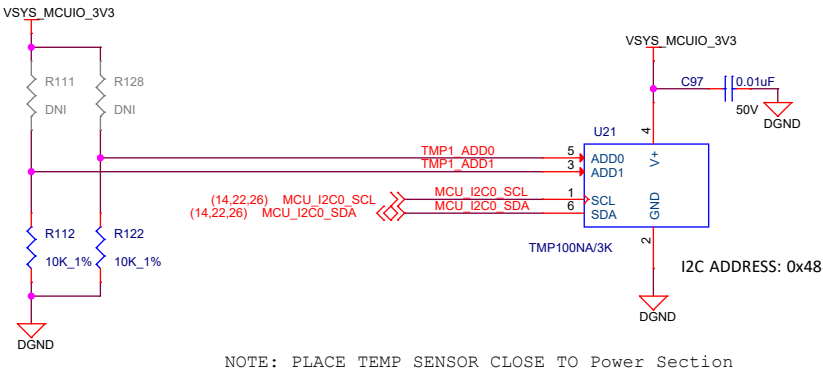
I2C for BOARD ID EEPROMs



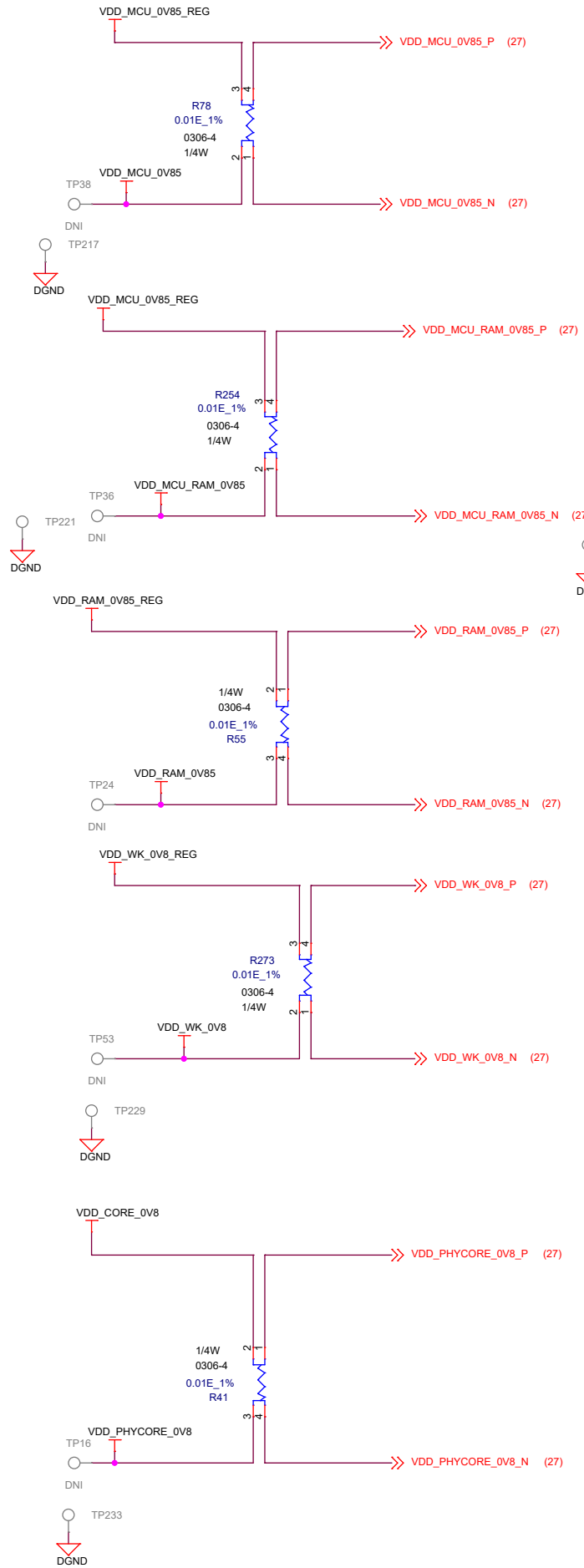
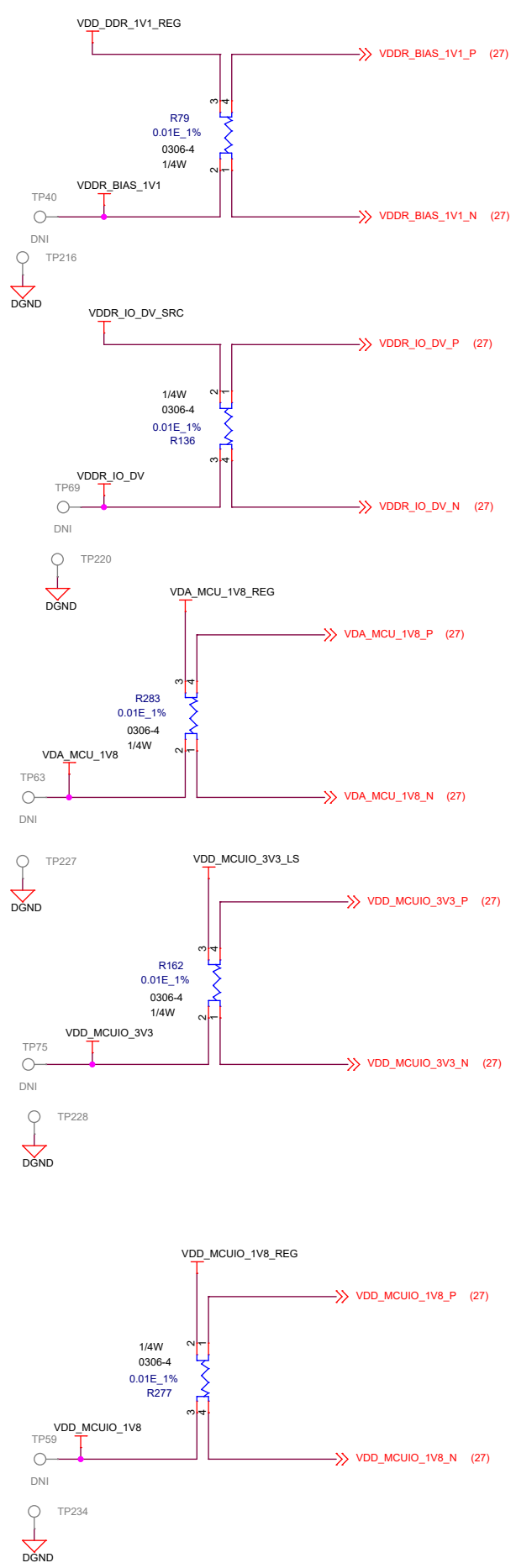
BOARD ID EEPROM (TI EVM Only)



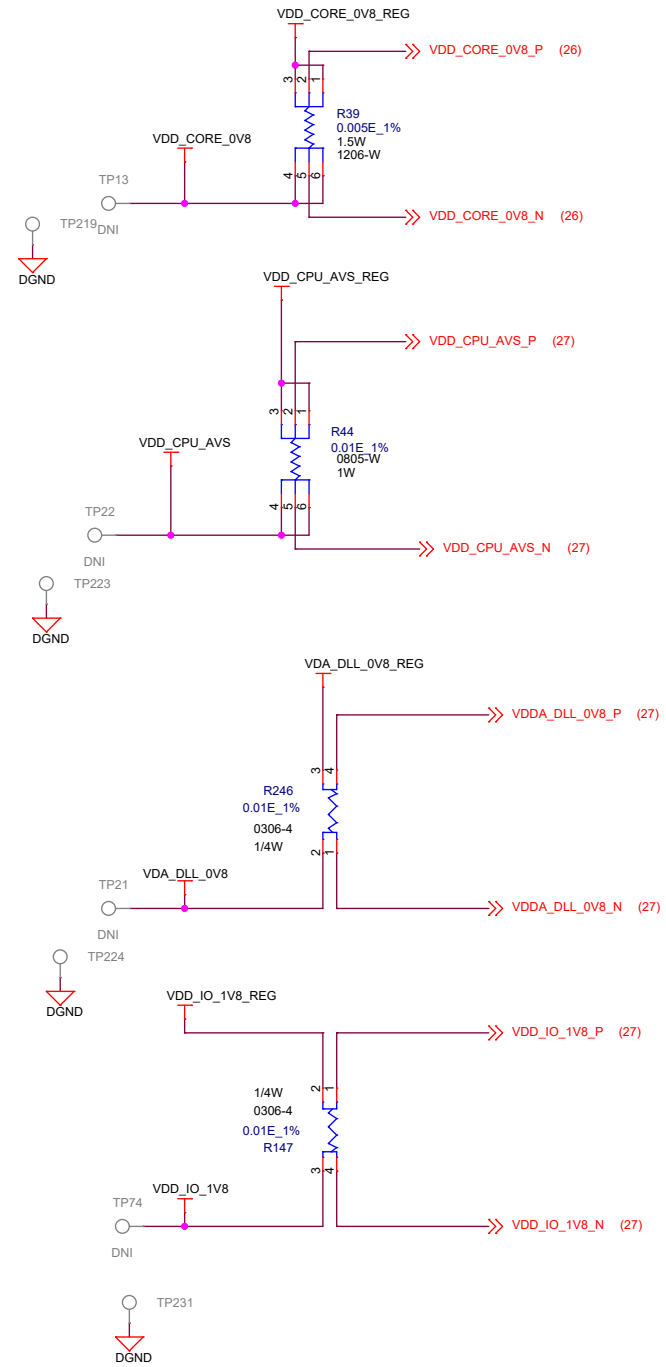
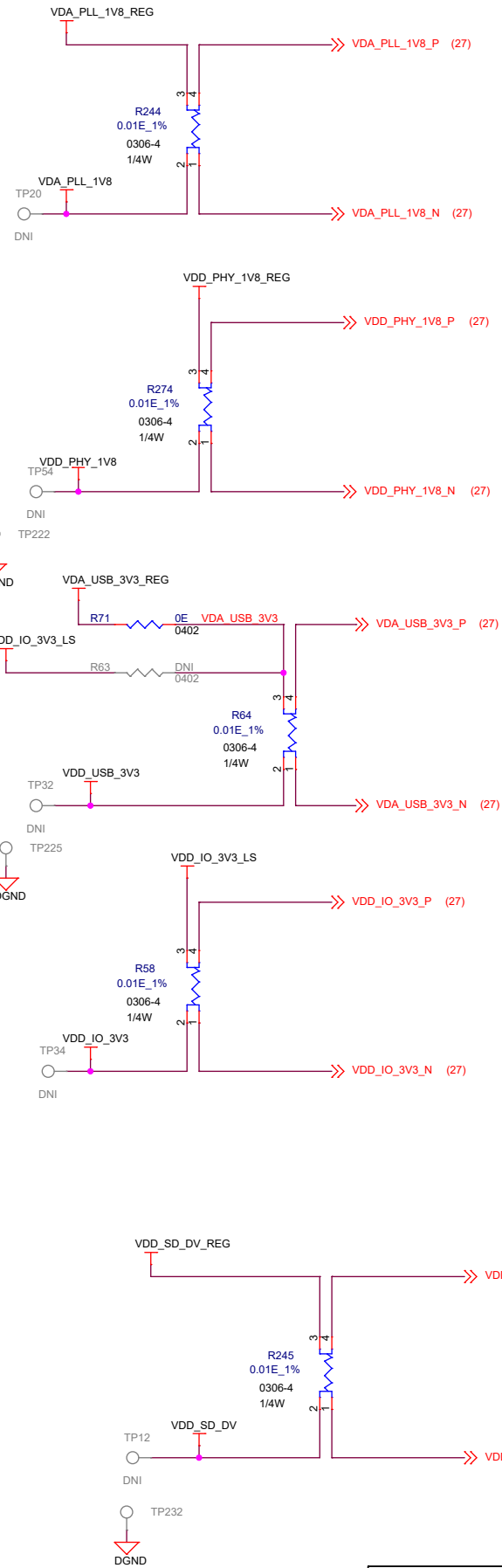
TEMPERATURE SENSORS (TI EVM Only)



SOC Current Sense Resistors

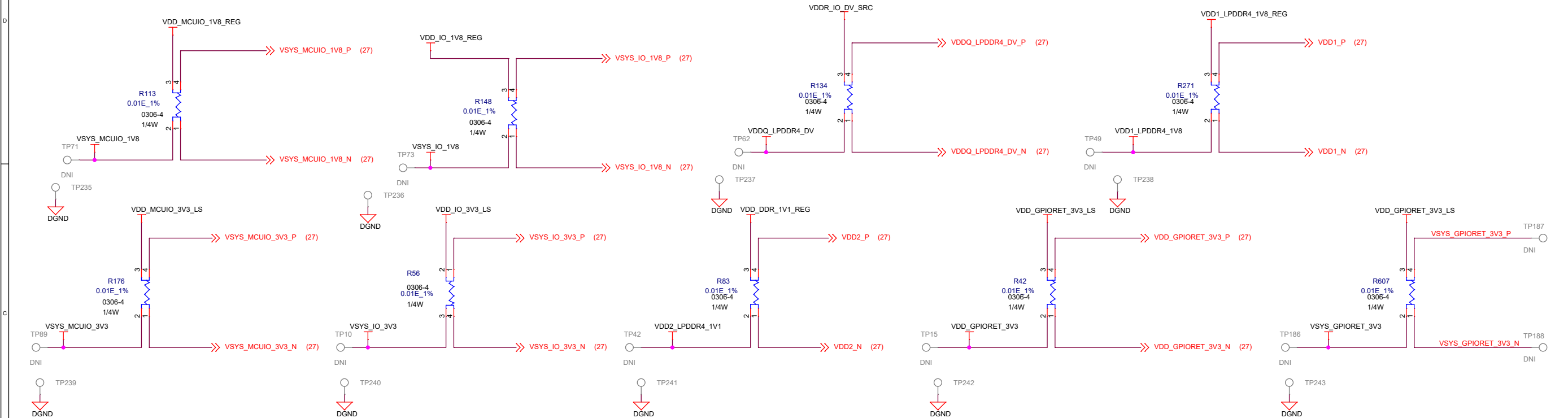


EVM development & evaluation test circuitry (TI EVM Only)

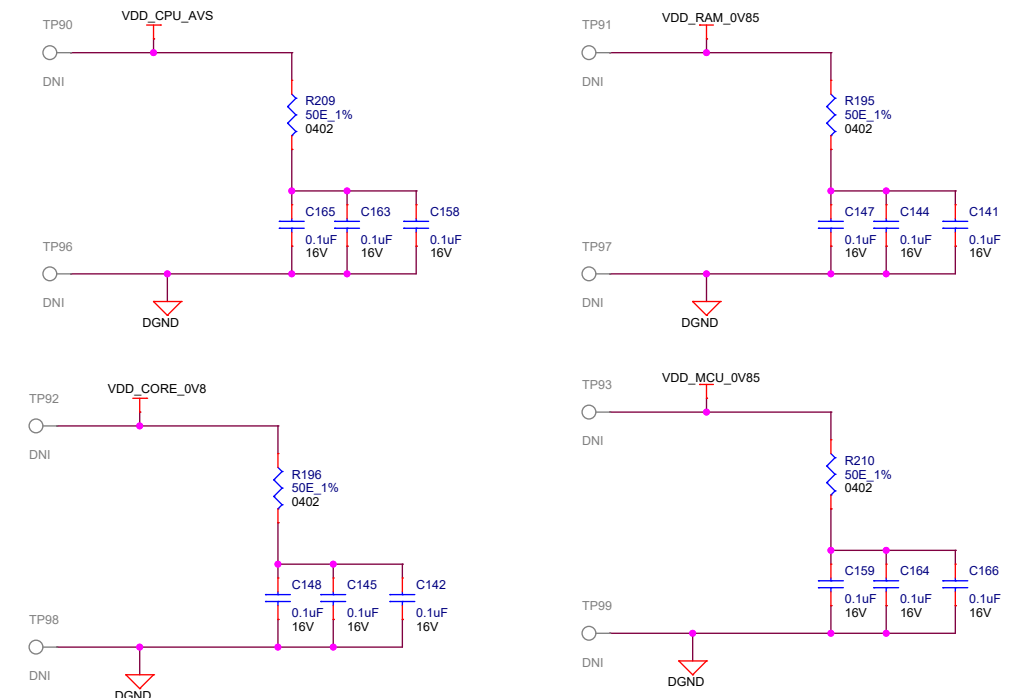


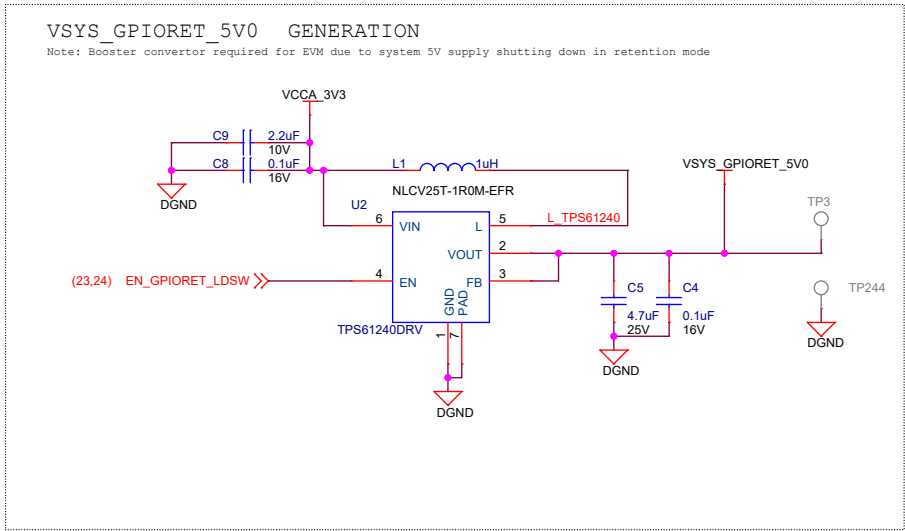
EVM development & evaluation test circuitry
(TI EVM Only)

Peripheral Current Sense Resistors

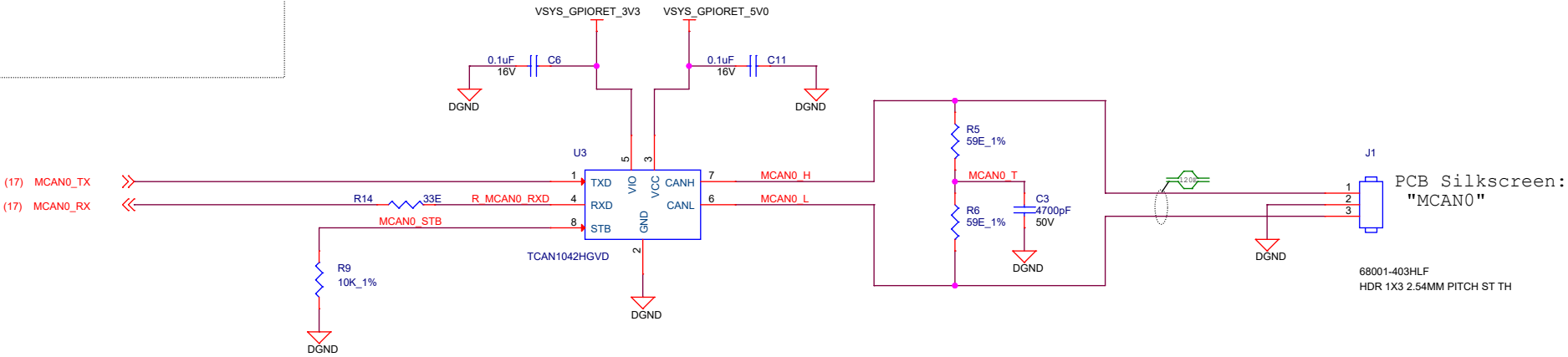


Supply Rail Kelvin Sensing



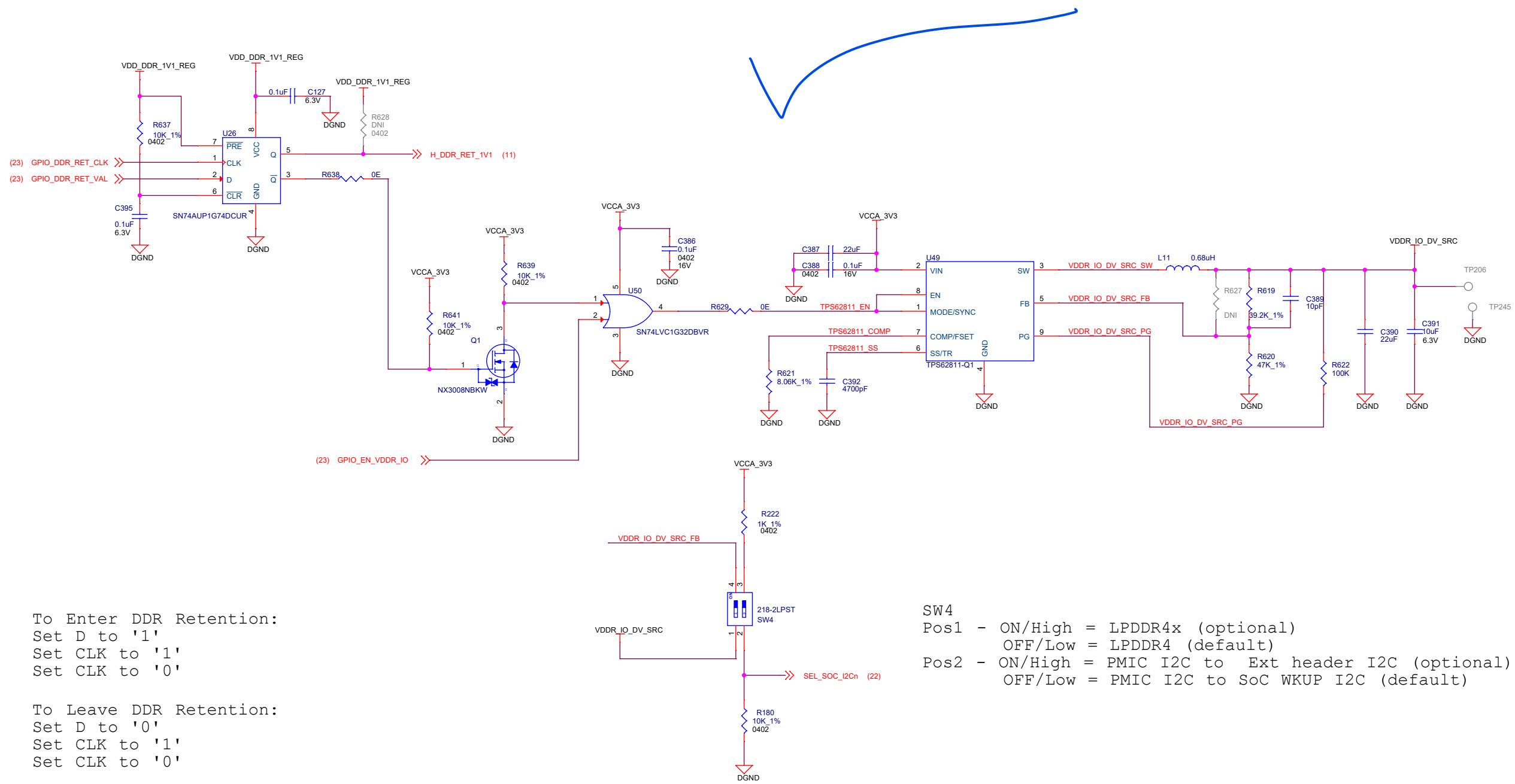


CAN TRANSCEIVER



EVM development & evaluation test circuitry
(TI EVM Only)

LPDDR4/4X POWER SUPPLY OPTION



To Enter DDR Retention:
Set D to '1'
Set CLK to '1'
Set CLK to '0'

To Leave DDR Retention:
Set D to '0'
Set CLK to '1'
Set CLK to '0'

SW4
Pos1 - ON/High = LPDDR4x (optional)
 OFF/Low = LPDDR4 (default)
Pos2 - ON/High = PMIC I2C to Ext header I2C (optional)
 OFF/Low = PMIC I2C to SoC WKUP I2C (default)

EVM Development & Evaluation test circuitry

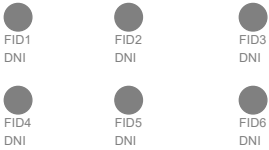
(TI EVM Only)

NOTES, HW & LABELS

ASSEMBLY NOTES

- 1. All MSL components should be baked as per JEDEC standard.
- 2. PCB should be baked at 120 degree for 8 hours.
- 3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
- 4. These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6. Provide serial numbers to the assembled boards for identification.
- 7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

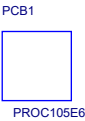
FIDUCIALS



SOCKET & PROCESSOR AS ACCESSORIES



BARE PCB



LABELS

Board Serial No.



Assembly Revision.



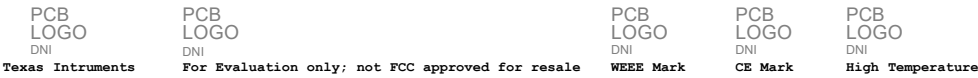
EVM Orderable No.



Orderable Part Numbers

Variant	Label Text
001 = Soldered GP SoC	J7200XSOMG01EVM
002 = Soldered HS SoC	J7200XSOMH01EVM
003 = Socketed SoC	J7200XSOMS01EVM

LOGOs



Project :

J7 EVM



Title
HARDWARE SCHEMATICS

Size
C
PROC105 001 J7200XSOMG01EVM

Rev

E6

Date: Tuesday, August 25, 2020 Sheet 33 of 34

SI_SIMULATION_COUPON_BD

Note: Test coupon not part of EVM design, to be used for TI test only

